



HY17P60B

Datasheet

**8-Bit RISC-like Mixed Signal Microcontroller
Embedded 19-Bit $\Sigma\Delta$ ADC
With Low Noise OPAMP & 4x20 LCD**

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1. Features

- **8-Bit RISC-like Mixed Signal Microcontroller**
 - 71 high performance H08D instruction sets
 - Hardware Lookup table
 - Power On/ Brown Out 1/ Brown Out 2
 - WDT/MCLR Reset
 - Support Assembly & C compiler environment
- **Operating Voltage and Temperature Range**
 - Digital Circuit: 2.2V ~ 5.5V
 - Analog Circuit: 2.4V ~ 4.5V
 - Operating Temperature: - 40°C ~ 85°C
- **8k Word OTP (One Time Programmable)**
 - Program memory, 512Byte data memory
- **High resolution $\Sigma\Delta$ ADC**
 - Max. Sampling Frequency up to 1MHz
 - Oversampling Freq. setting:32~61440
 - Second/third order comb filter with conversion frequency of 30.72ksps
 - ADC Gain: x1/2, x1, x2, x4, x8
 - Zero input/output voltage
 - High input impedance (built-in input buffer)
 - Built-in absolute temperature sensor
- **Built-in digital signal processing (DSP) realizes digital AC RMS, Peak Hold and other digital calculation functions**
- **Multi-functional comparator**
 - LVD low voltage detection function with multi-stage detection voltage setting and external input voltage detection function
 - Equipped with delay and latch function, reducing glitch
- **OPA (Low Noise Operational Amplifier)**
 - Combined with external components to achieve AC rectifier filter circuit
- **Analog voltage (VDDA) source equipping with 10mA regulated voltage source output ability, quick start function**
- **1.2V internal analog circuit common-ground voltage source**
- **4x20 LCD driver**
 - 1/4 Duty 、 1/3 Bias
 - Built-in charge pump regulated circuit, providing multiple LCD bias voltage
 - There are 2 LCD ports with digital input and output ports
- **3 sets of 24-bit programmable counters for frequency and duty cycle measurement.**
- **8-bit Timer A1**
- **16-bit Timer B module with PWM function**
- **UART 、 I²C(Master/Slave) module**
- **Built-In EPROM (BIE) ,Built-in 2.75V low voltage programming control circuit**
- **Built-in Brownout and Watch dog timer to prevent the CPU into the crash mode**
- **External Crystal oscillator: 32768Hz or 1M~16MHz.Built-in HAO oscillator, four HAO frequency can be selected: 4.9152MHz, 9. 8304MHz.Mode multiple CPU clock switching options, allowing users to achieve the best power saving plan**
 - Operation mode
 - Idle mode: LPO 14.5kHz
 - Sleep mode
- **Support 8 stack levels.**
- **Package Type**
 - LQFP64
 - QFN32
- **Applications**
 - 2000 Counts DMM
 - Measurement Device
 - Infrared temperature measurement
 - Weighing

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Embedded 19-Bit $\Sigma\Delta$ ADC with LNA OPAMP & 4x20 LCD

2. Pin Definition

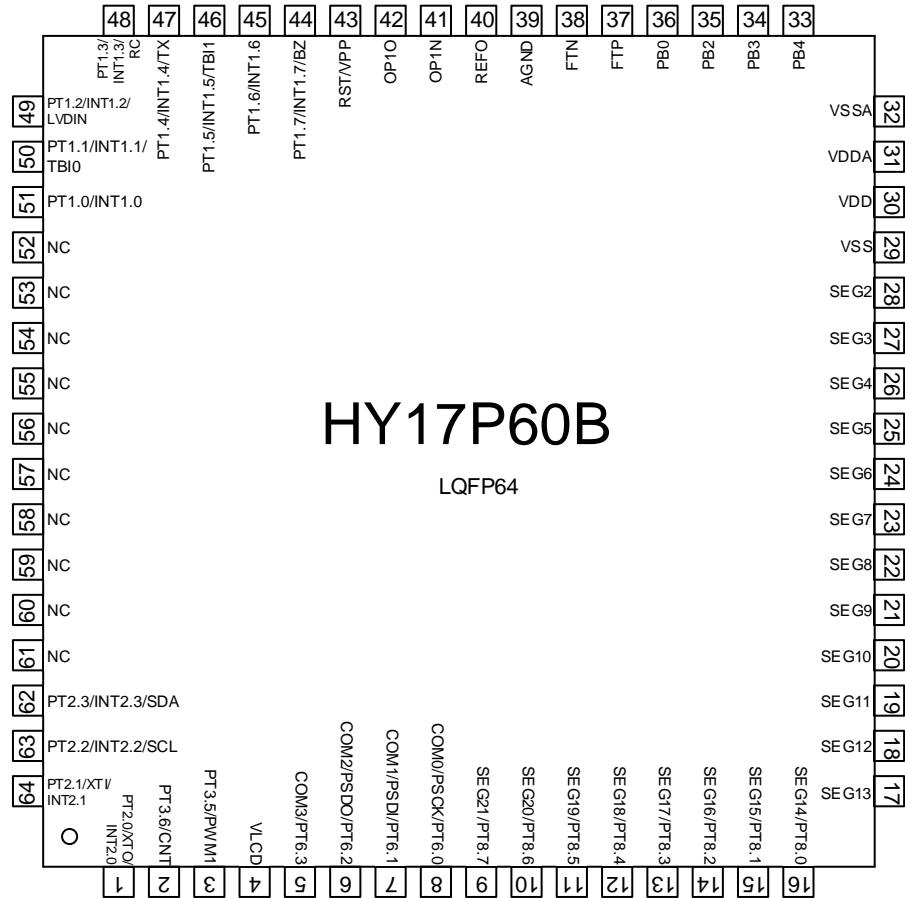


Figure2-1 HY17P60B LQFP64 pin diagram

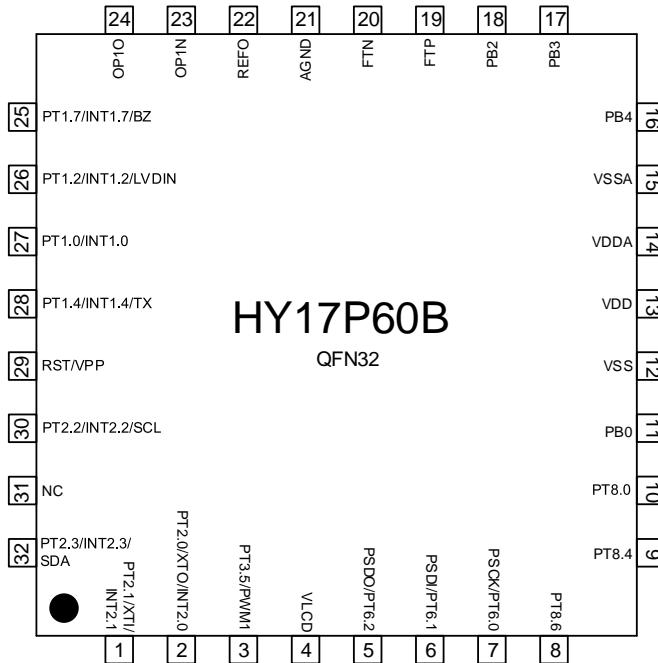


Figure2-2 HY17P60B QFN32 pin diagram

2.1. Pin Description

"I/O" Input/Output, "I" Input, "O" Output, "S" Schmitt Trigger, "C" CMOS, "P" Power, "A" Analog

Pin No.		Name	Characteristic		Description
LQFP64	QFN32		I/O	Type	
1	2	PT2.0/XTO/INT2.0		S/C	Digital input/output
			PT2.0	I/O	Output port of external oscillator
			XTO	A	Interrupt source INT2.0
2	-	PT3.6/CNT		S/C	Digital input/output
			PT3.6	I/O	Input port of frequency counter
3	3	PT3.5/PWM1		S/C	Digital input/output
			PT3.5	I/O	PWM1 output port
4	4	VLCD		P	Voltage source of LCD · 1~10uF need. (Source: VDD)
5	-	COM3/PT6.3		A	COM3 output of LCD
			COM3	O	Digital input/output
6	5	COM2/PSDO/PT6.2		S/C	COM2 output of LCD
			COM2	O	PSDO of OTP read/write interface
			PT6.2	I/O	Digital input/output
7	6	COM1/PSDI/PT6.1		A	COM1 output of LCD
			COM1	O	PSDI of OTP read/write interface
			PT6.1	I/O	Digital input/output
8	7	COM0/PSCK/PT6.0		S/C	COM0 output of LCD
			COM0	O	PSCK of OTP read/write interface
			PT6.0	I/O	Digital input/output
9	-	SEG21/PT8.7		A	Segment output of LCD
			SEG21	O	Digital input/output
10	8	SEG20/PT8.6		S/C	Segment output of LCD
			PT8.6	I/O	Digital input/output

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Pin No.		Name	Characteristic		Description
LQFP64	QFN32		I/O	Type	
11	-	SEG19/PT8.5 SEG19 PT8.5	O I/O	A S/C	Segment output of LCD Digital input/output
12	9	SEG18/PT8.4 SEG18 PT8.4	O I/O	A S/C	Segment output of LCD Digital input/output
13	-	SEG17/PT8.3 SEG17 PT8.3	O I/O	A S/C	Segment output of LCD Digital input/output
14	-	SEG16/PT8.2 SEG16 PT8.2	O I/O	A S/C	Segment output of LCD Digital input/output
15	-	SEG15/PT8.1 SEG15 PT8.1	O I/O	A S/C	Segment output of LCD Digital input/output
16	10	SEG14/PT8.0 SEG14 PT8.0	O I/O	A S/C	Segment output of LCD Digital input/output
17	-	SEG13	O	A	Segment output of LCD
18	-	SEG12	O	A	Segment output of LCD
19	-	SEG11	O	A	Segment output of LCD
20	-	SEG10	O	A	Segment output of LCD
21	-	SEG9	O	A	Segment output of LCD
22	-	SEG8	O	A	Segment output of LCD
23	-	SEG7	O	A	Segment output of LCD
24	-	SEG6	O	A	Segment output of LCD
25	-	SEG5	O	A	Segment output of LCD
26	-	SEG4	O	A	Segment output of LCD
27	-	SEG3	O	A	Segment output of LCD
28	-	SEG2	O	A	Segment output of LCD
29	12	VSS	P	P	Ground end of IC operation voltage source
30	13	VDD	P	P	Voltage source of IC operation · 1~10uF need.

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Embedded 19-Bit $\Sigma\Delta$ ADC with LNA OPAMP & 4x20 LCD



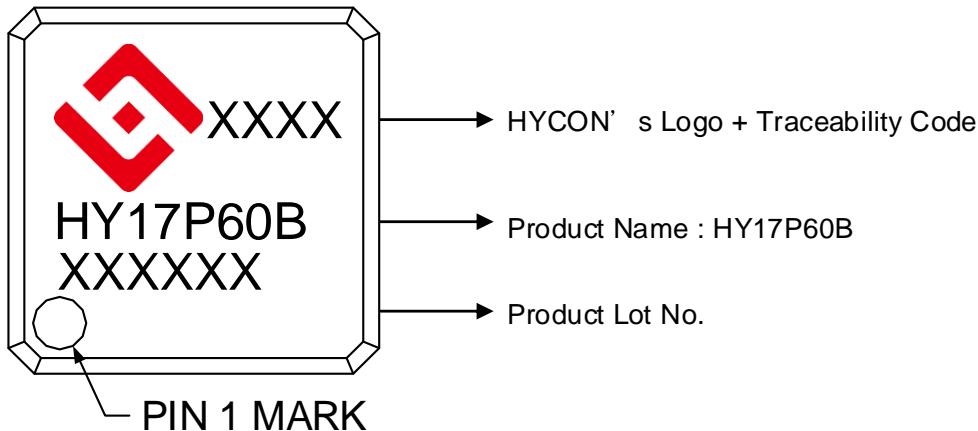
Pin No.		Name	Characteristic		Description
LQFP64	QFN32		I/O	Type	
31	14	VDDA	P	P	Analog circuit voltage source (source: VDD)
32	15	VSSA	P	P	Ground end of IC operation voltage source
33	16	PB4	I	A	Analog input channel
34	17	PB3	I	A	Analog input channel
35	18	PB2	I	A	Analog input channel
36	11	PB0	I	A	Analog input channel
37	19	FTP	I/O	A	Capacitor connect port of pre-filter
38	20	FTN	I/O	A	Capacitor connect port of pre-filter
39	21	AGND	P	P	Analog power ground end (source: VDDA)
40	22	REFO	P	P	Voltage reference port (source: VDDA)
41	23	OP1N	I	A	OPAMP(OP1) negative input terminal
42	24	OP1O	O	A	OPAMP(OP1) output terminal
43	29	RST/VPP	I	S	Reset IC (Low active)
			P	P	EPROM read/write voltage source
44	25	PT1.7/INT1.7/BZ	I/O	S/C	Digital input/output
		PT1.7	I	S	Interrupt source INT1.7
		BZ	O	C	Buzzer output port
45	-	PT1.6/INT1.6	I/O	S/C	Digital input/output
		PT1.6	I	S	Interrupt source INT1.6
46	-	PT1.5/INT1.5/TBI1	I/O	S/C	Digital input/output
		PT1.5	I	S	Interrupt source INT1.5
		TBI1	I	S	TimerB CPI Source Input pin
47	28	PT1.4/INT1.4/TX	I/O	S/C	Digital input/output
		PT1.4	I	S	Interrupt source INT1.4
		TX	O	C	UART communication Transfer pin

Pin No.		Name	Characteristic		Description
LQFP64	QFN32		I/O	Type	
48	-	PT1.3/INT1.3/RC	PT1.3	I/O	S/C
				I	S
				I	S
				Digital input/output Interrupt source INT1.3 UART communication Receiver Pin	
49	26	PT1.2/INT1.2/LVDIN	PT1.2	I/O	S/C
				I	S
				A	A
				Digital input/output Interrupt source INT1.2 LVD external signal input port	
50	-	PT1.1/INT1.1/TBI0	PT1.1	I/O	S/C
				I	S
				I	S
				Digital input/output Interrupt source INT1.1 TimerB CPI Source Input pin	
51	27	PT1.0/INT1.0	PT1.0	I/O	S/C
				I	S
				Digital input/output Interrupt source INT1.0	
52~61	31	NC	-	-	Unused (not connectable)
62	32	PT2.3/INT2.3/SDA	PT2.3	I/O	S/C
				I	S
				I/O	S
				Digital input/output Interrupt source INT2.3 SDA of I ² C communication interface	
63	30	PT2.2/INT2.2/SCL	PT2.2	I/O	S/C
				I	S
				I/O	S
				Digital input/output Interrupt source INT2.2 SCL of I ² C communication interface	
64	1	PT2.1/XTI/INT2.1	PT2.1	I/O	S/C
				A	A
				I	S
				Digital input/output Input port of external oscillator Interrupt source INT2.1	

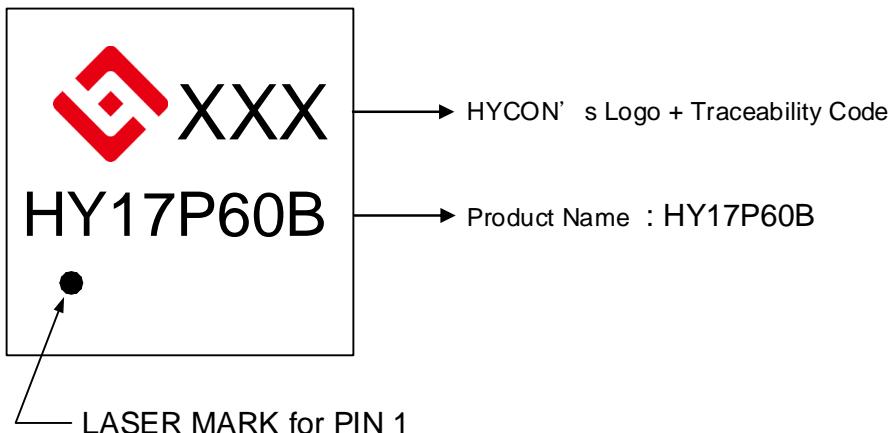
Table 2-1 Pin Definition and Pin Description

2.2. Package marking information

2.2.1. HY17P60B LQFP Package marking information



2.2.2. HY17P60B QFN Package marking information



3. Application Circuit

3.1. 2000 counts manual range DMM

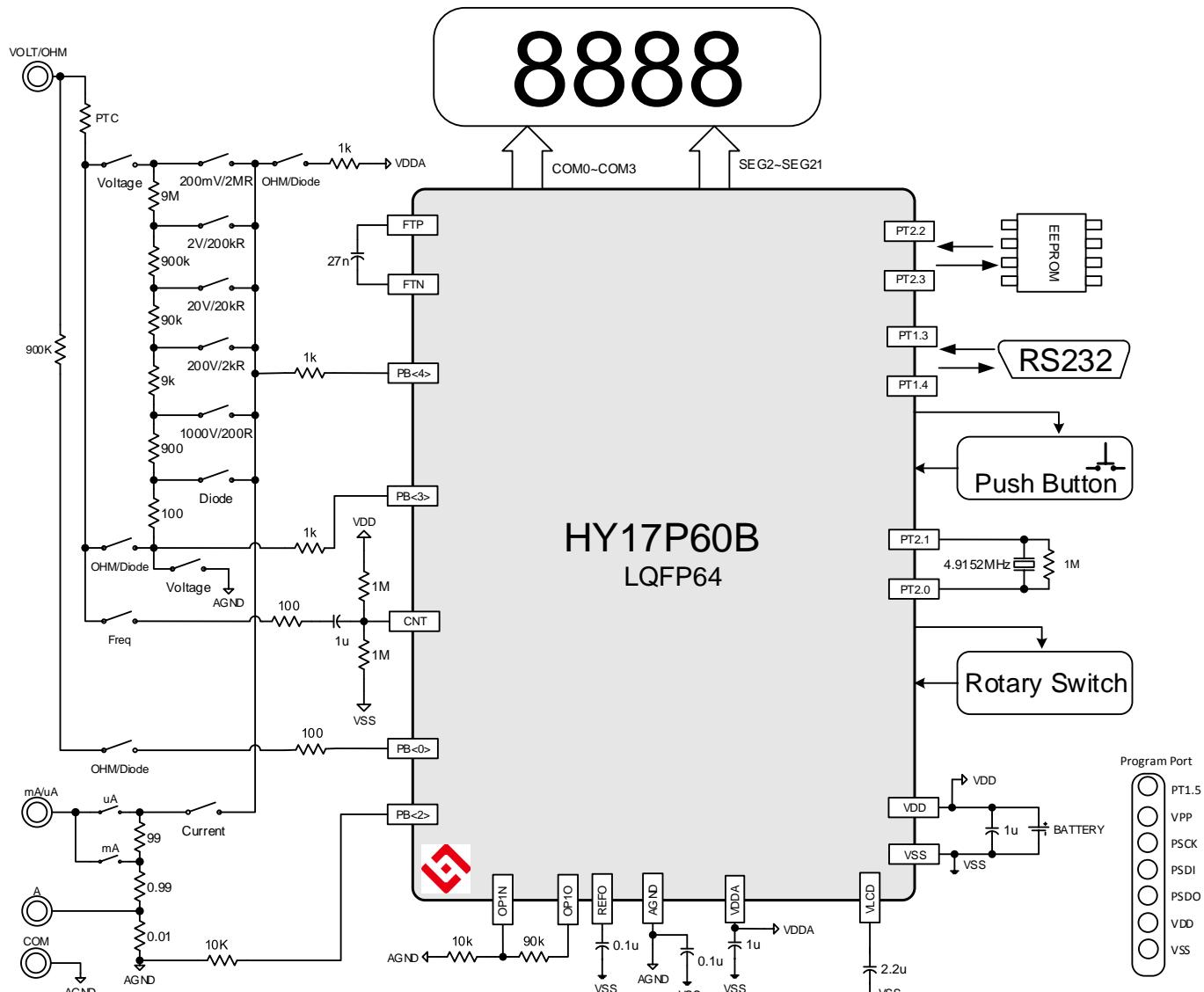


Figure 3-1 HY17P60B 2000 Counts manual range DMM application circuit

3.2. HY17P60B Infrared sensor application circuit

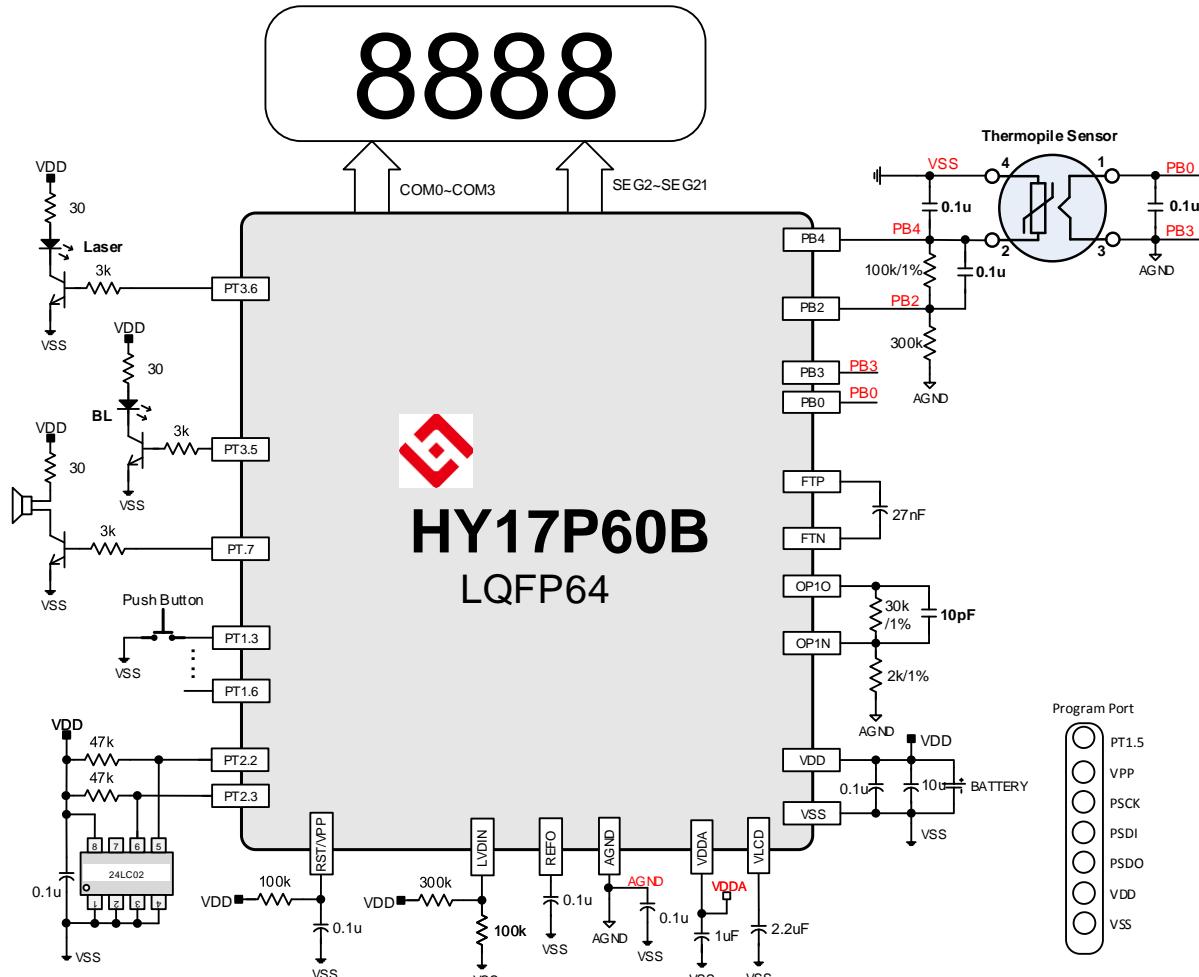


Figure 3-2 HY17P60B Infrared sensor application circuit

4. Function Outline

4.1. Internal Block Diagram

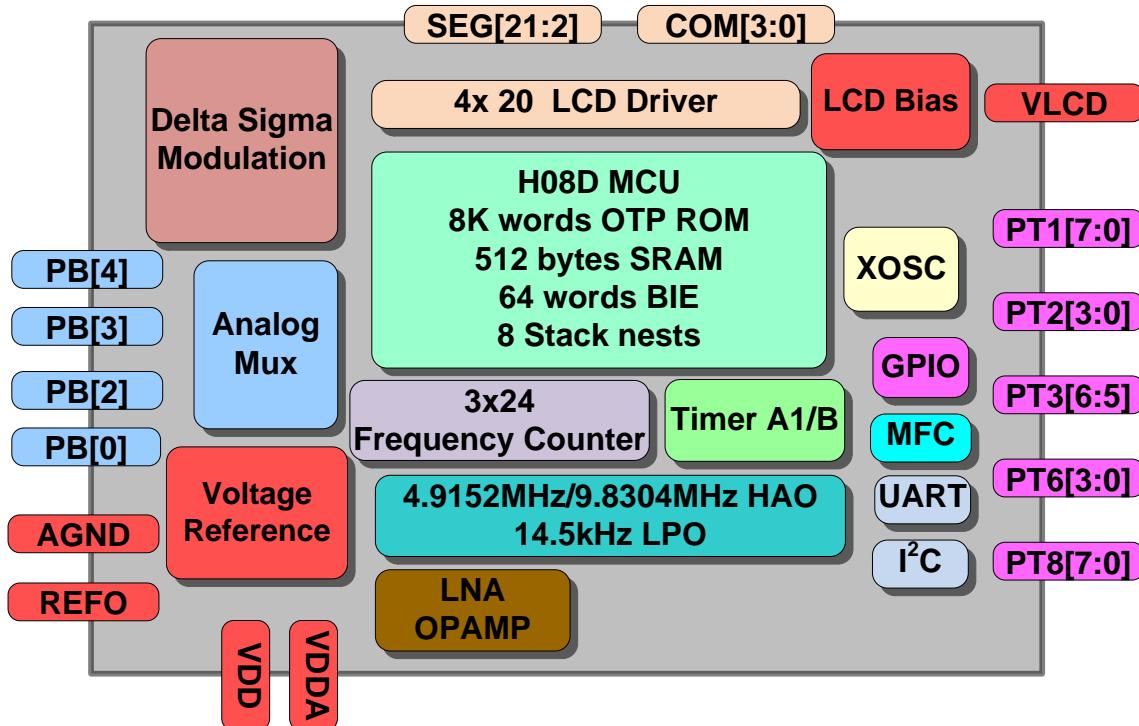


Figure 4-1 Internal Block Diagram

4.2. Related Manuals and Supporting Documents

IC Function Related Instruction Manual

DS-HY17P60B	HY17P60B Data Sheet
UG-HY17S68	HY17S68 User's Manual
APD-CORE005	H08D Instruction Set User's Manual

Development Tool Related Instruction Manual

APD-HY17PIDE001	HY17P Series Development Tool Software Instruction Manual
APD-HY17PIDE006	HY17S68-DK02 IDE Hardware Instruction Manual
APD-HYIDE013	Integrated Writer User's Manual
APD-HYIDE014	HY10000-WK08C Integrated Writer Online Update Manual
APD-OTP005	OTP programming pin information

Product Production Related Instruction Manual

APD-HY17PIDE004	HY17P Series HexLoader User's Manual
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4.3. ADC Network

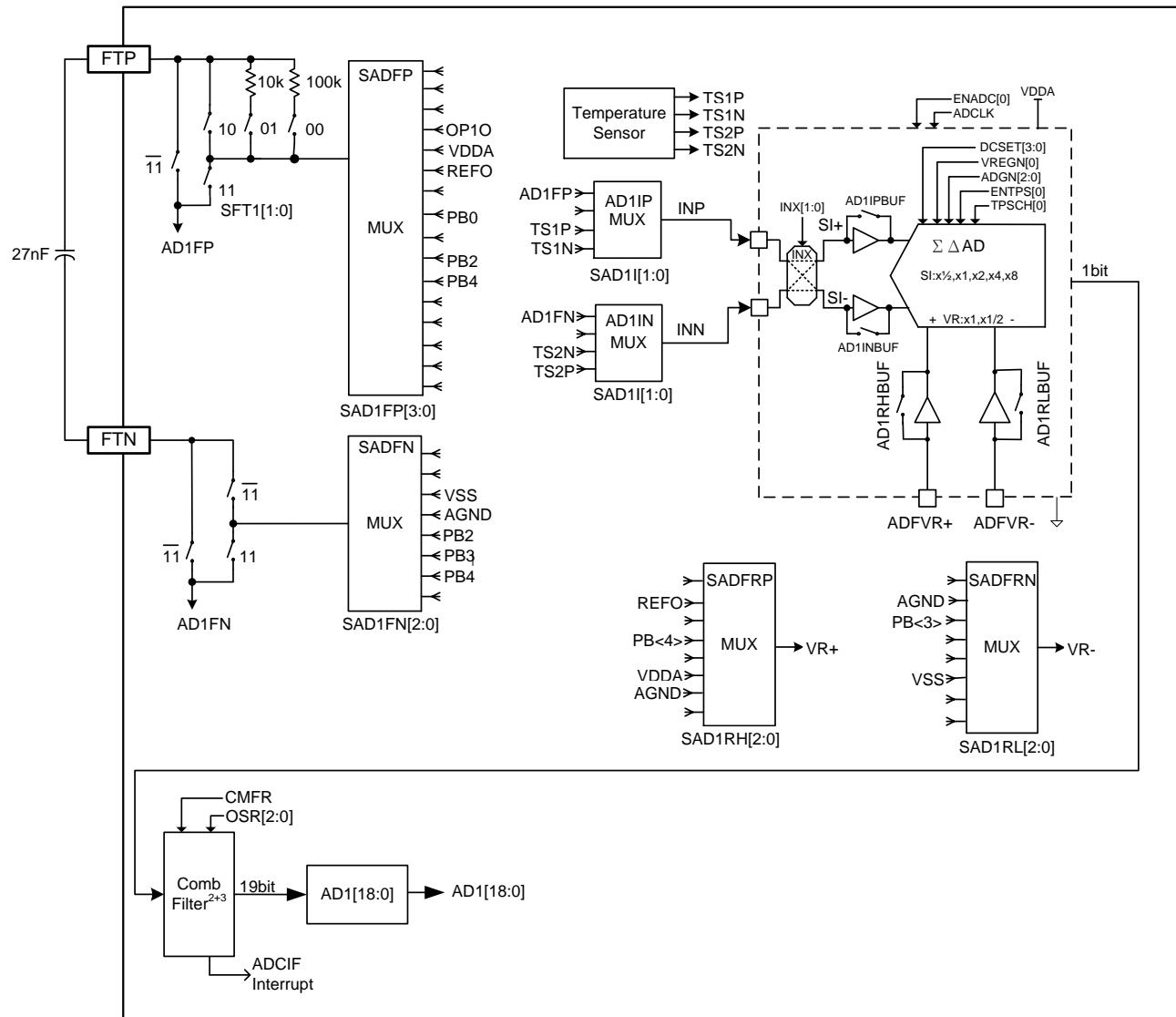


Figure 4-1 $\Sigma\Delta$ ADC Network block diagram

4.4. Digital Signal Processing(DSP)

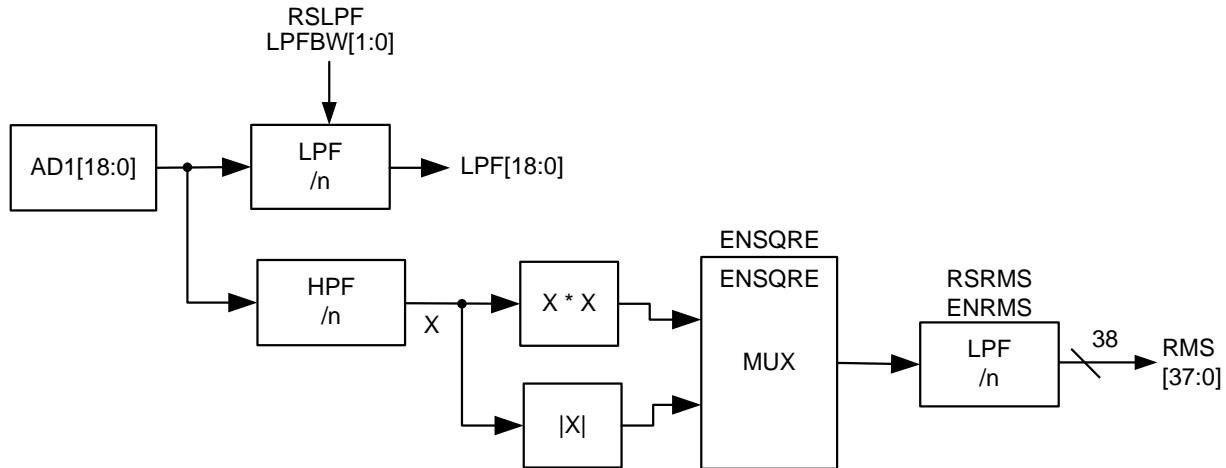


Figure 4-2 Digital Signal Processing(DSP) block diagram

4.5. Analog Input Network

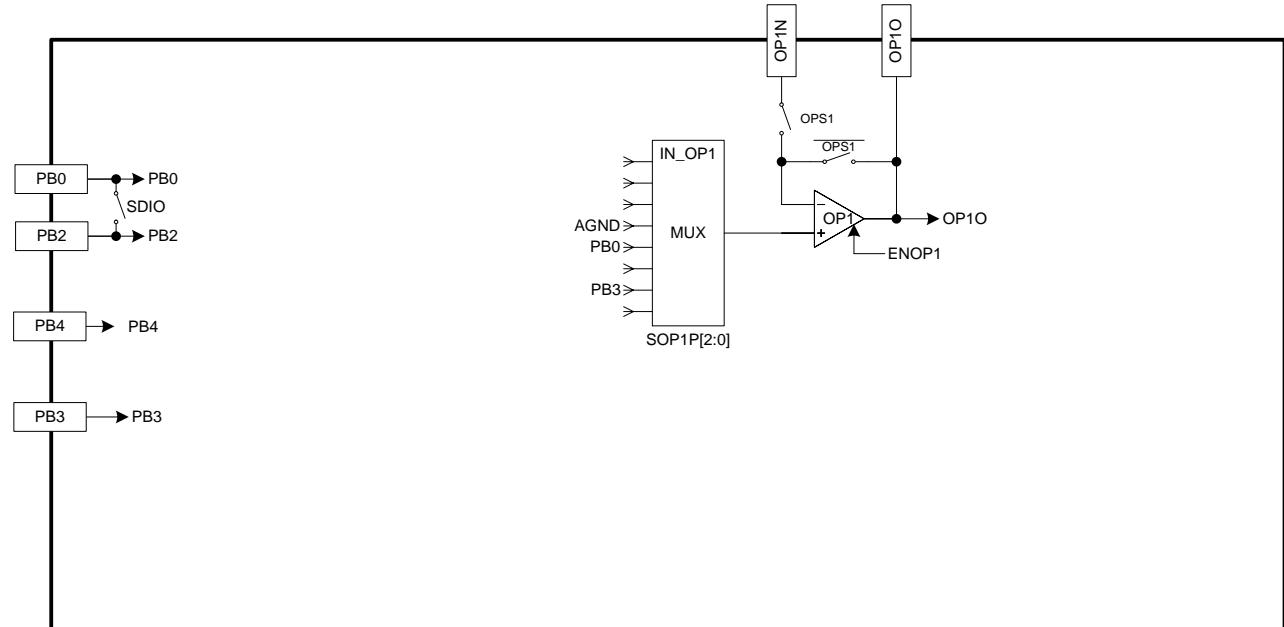


Figure 4-3 Analog Input Network block diagram

4.6. Clock System

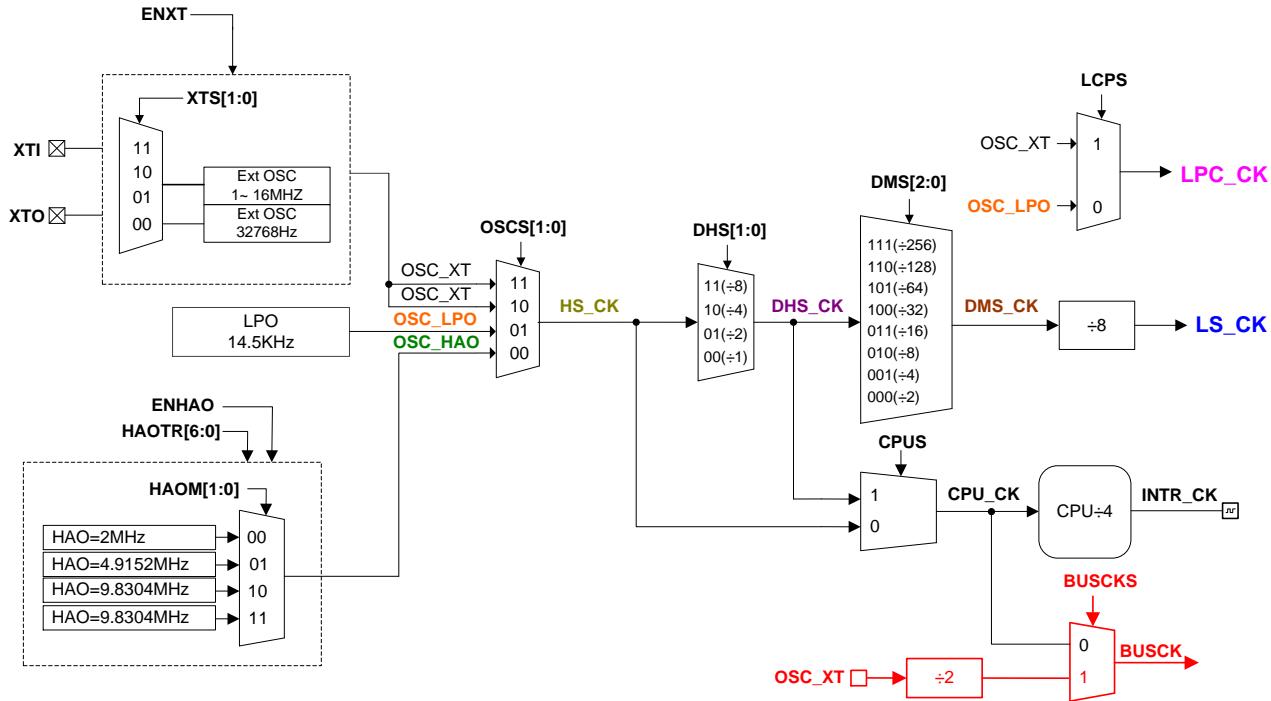


Figure 4-4 HY17P60B Clock System block diagram (—)

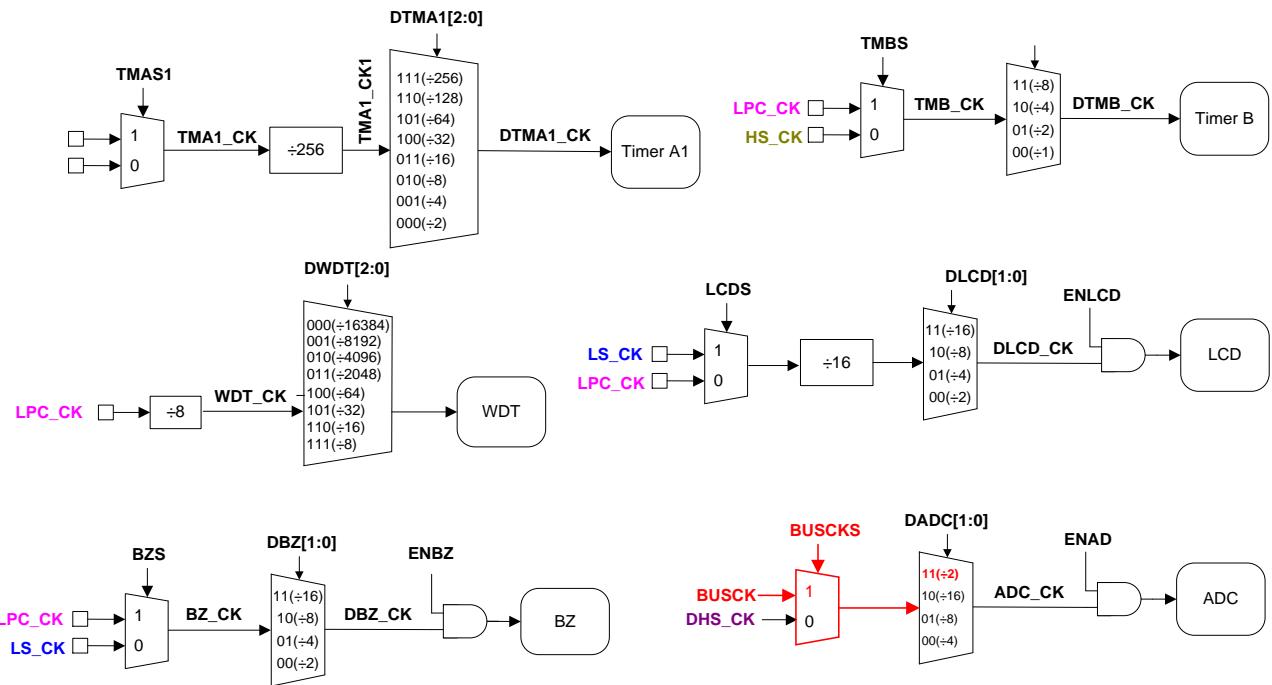


Figure 4-5 HY17P60B Clock System block diagram (—)

4.7. Multi-function Comparator

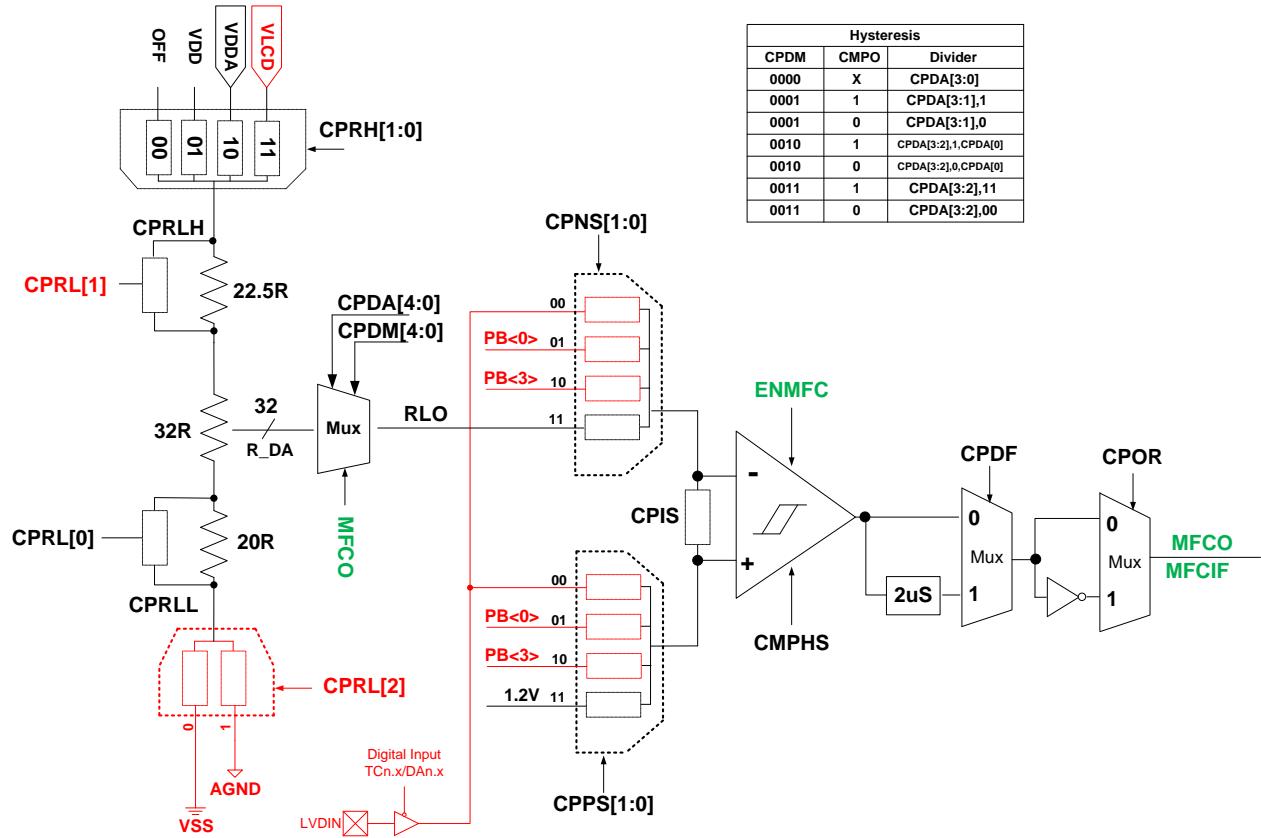


Figure 4-6 Multi-function Comparator block diagram

4.8. Reset

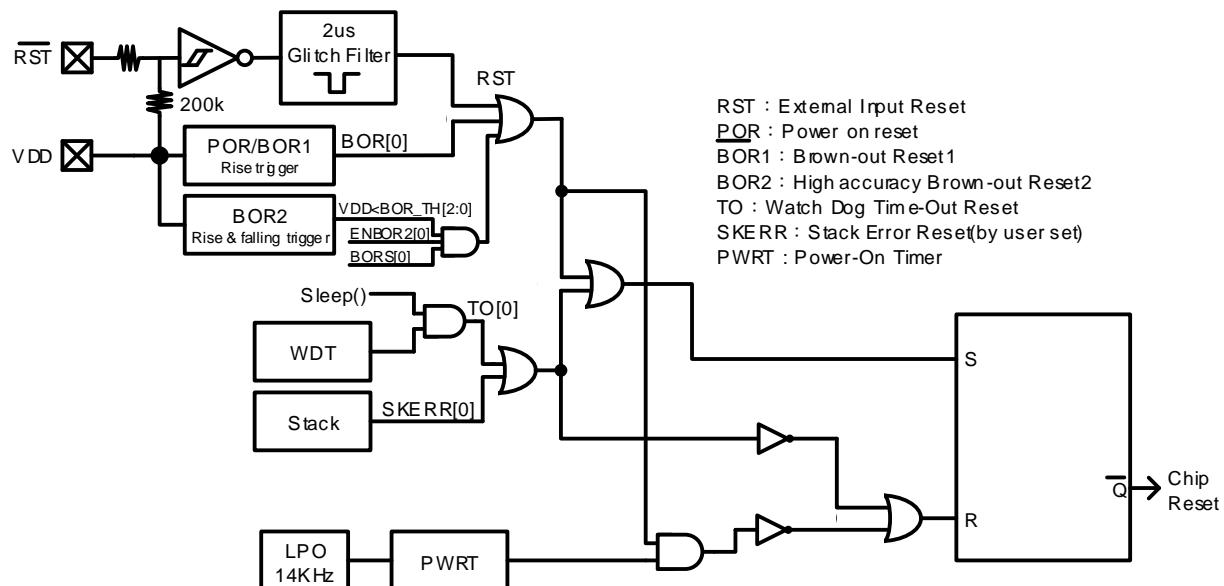


Figure 4-7 Reset block diagram

4.9. Power Diagram

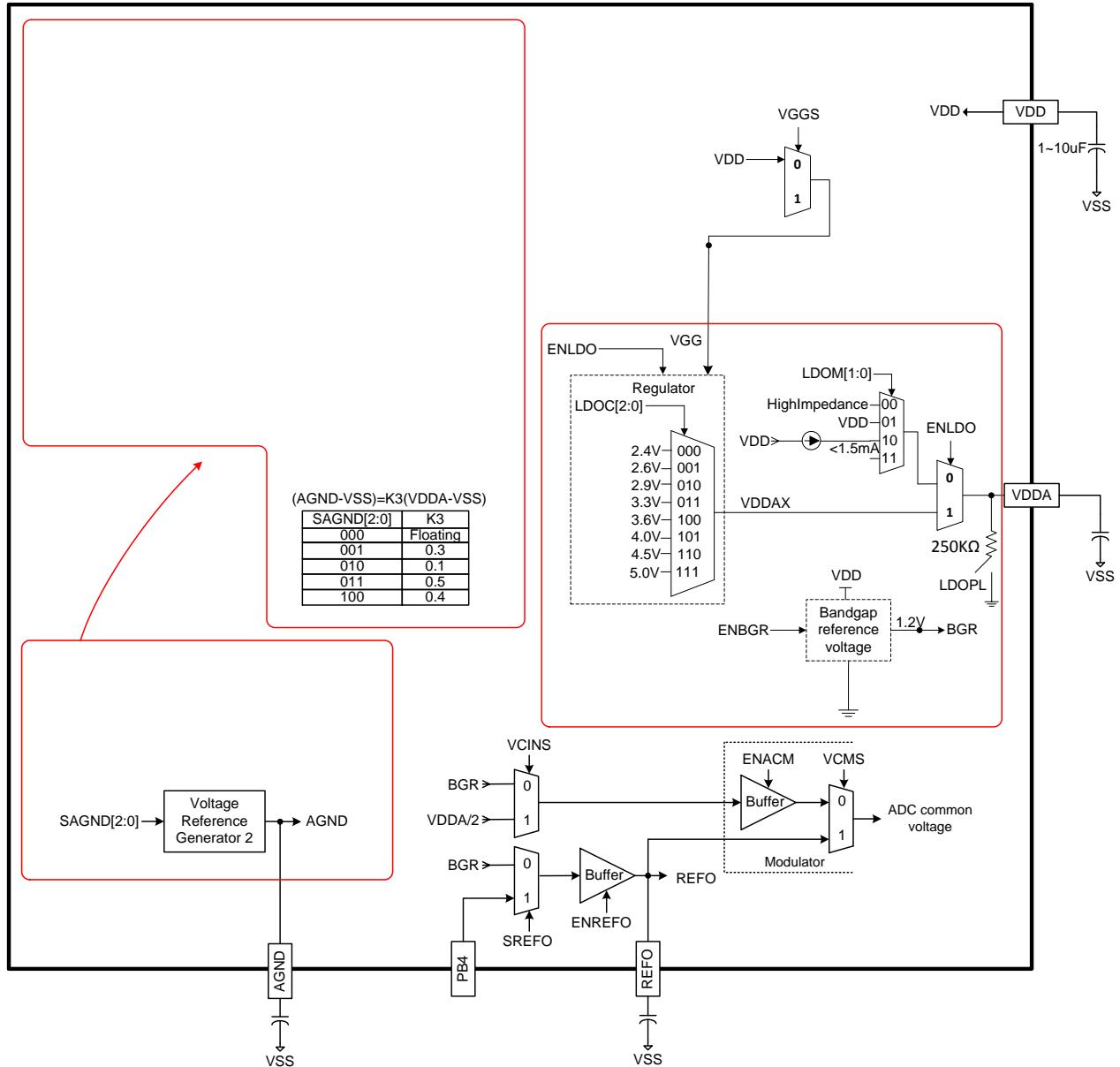


Figure 4-8 Power System block diagram

4.10. Frequency Counter 、 CNT Pin

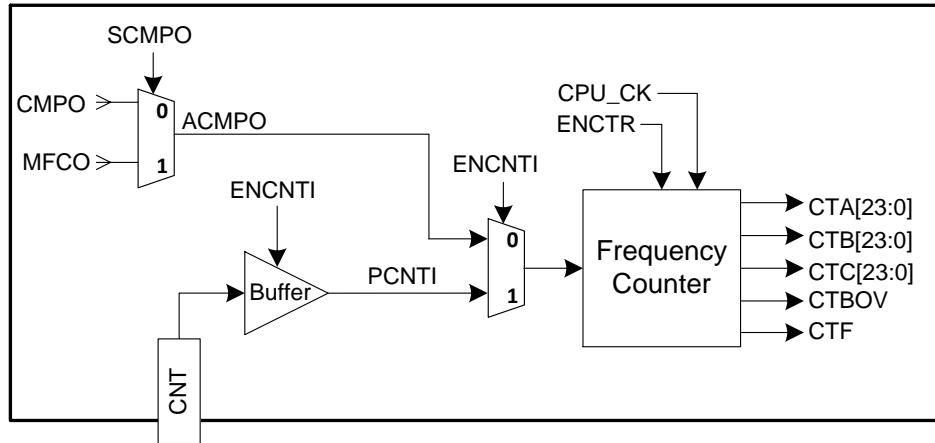


Figure 4-90 Frequency Counter block diagram

4.11. GPIO PORT1~3

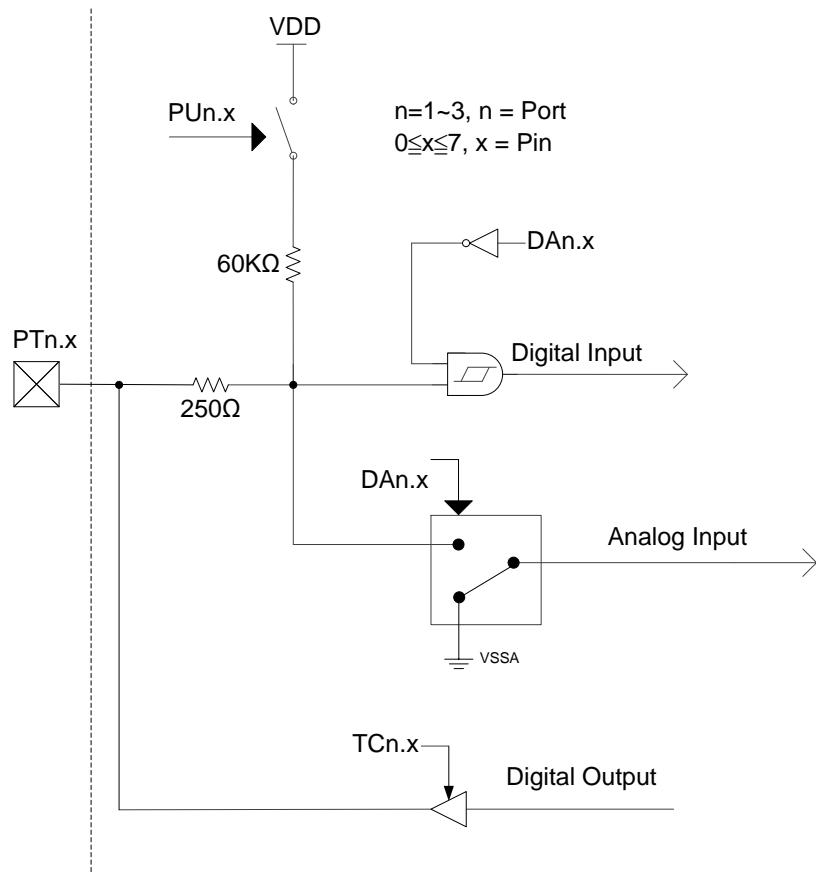


Figure 4-101 GPIO PORT1~3 block diagram

4.12. Watch Dog

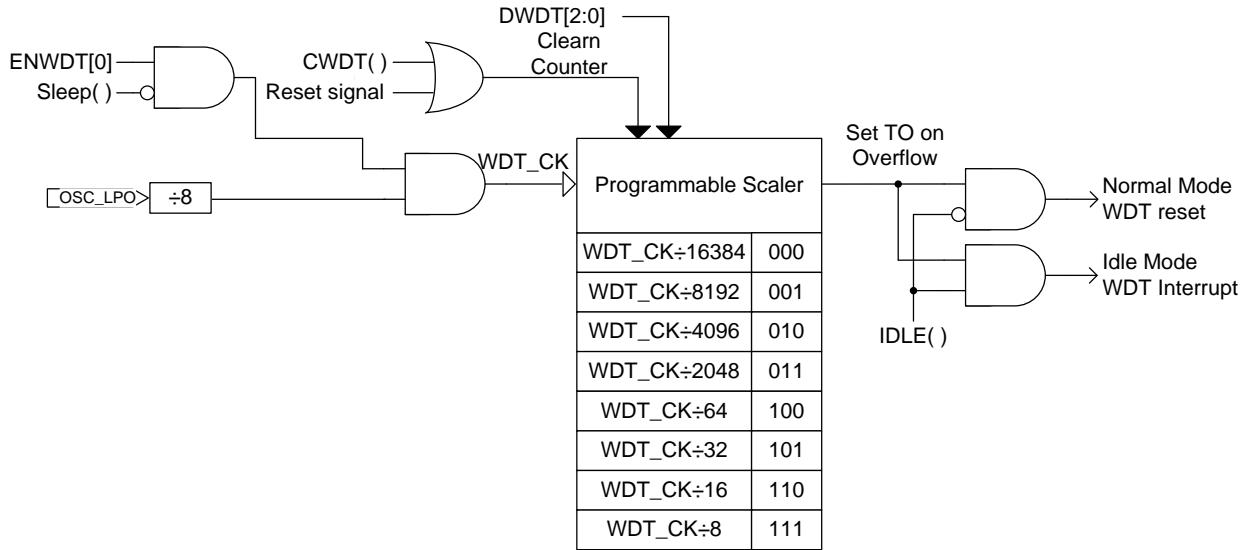


Figure 4-112 Watch Dog block diagram

4.13. 8-bit Timer A1

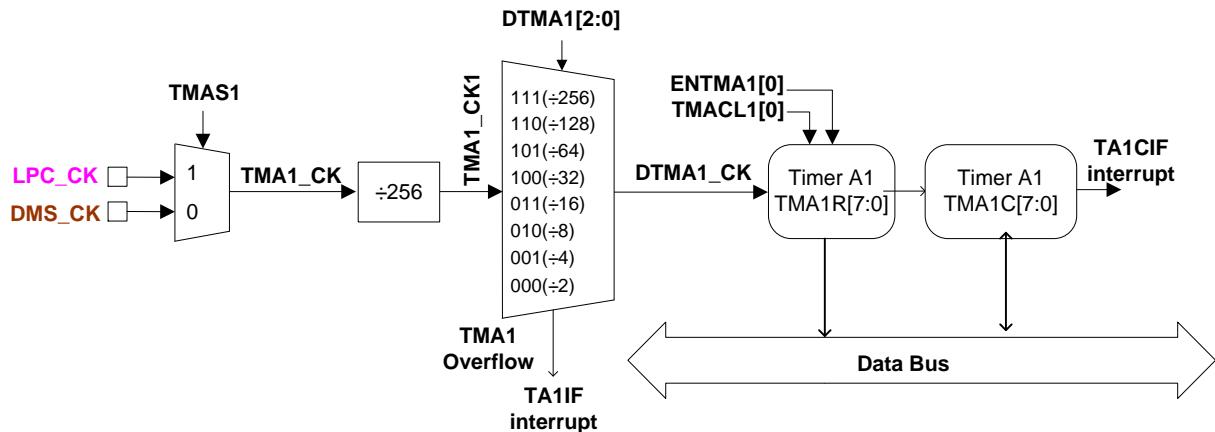


Figure 4-123 8-bit Timer A1 block diagram

4.14. 16-bit Timer B

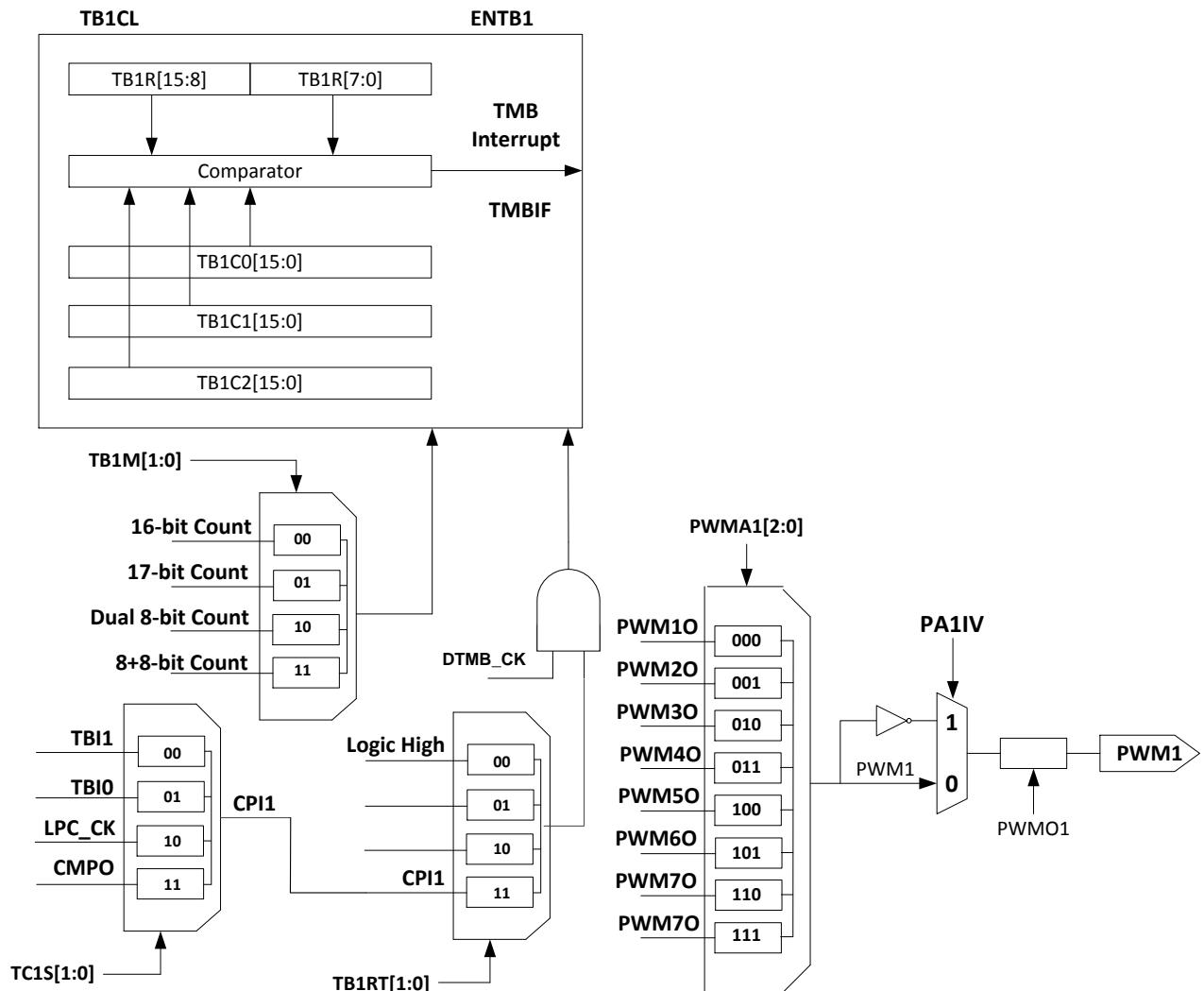


Figure 4-134 16-bit Timer B block diagram

4.15. LCD

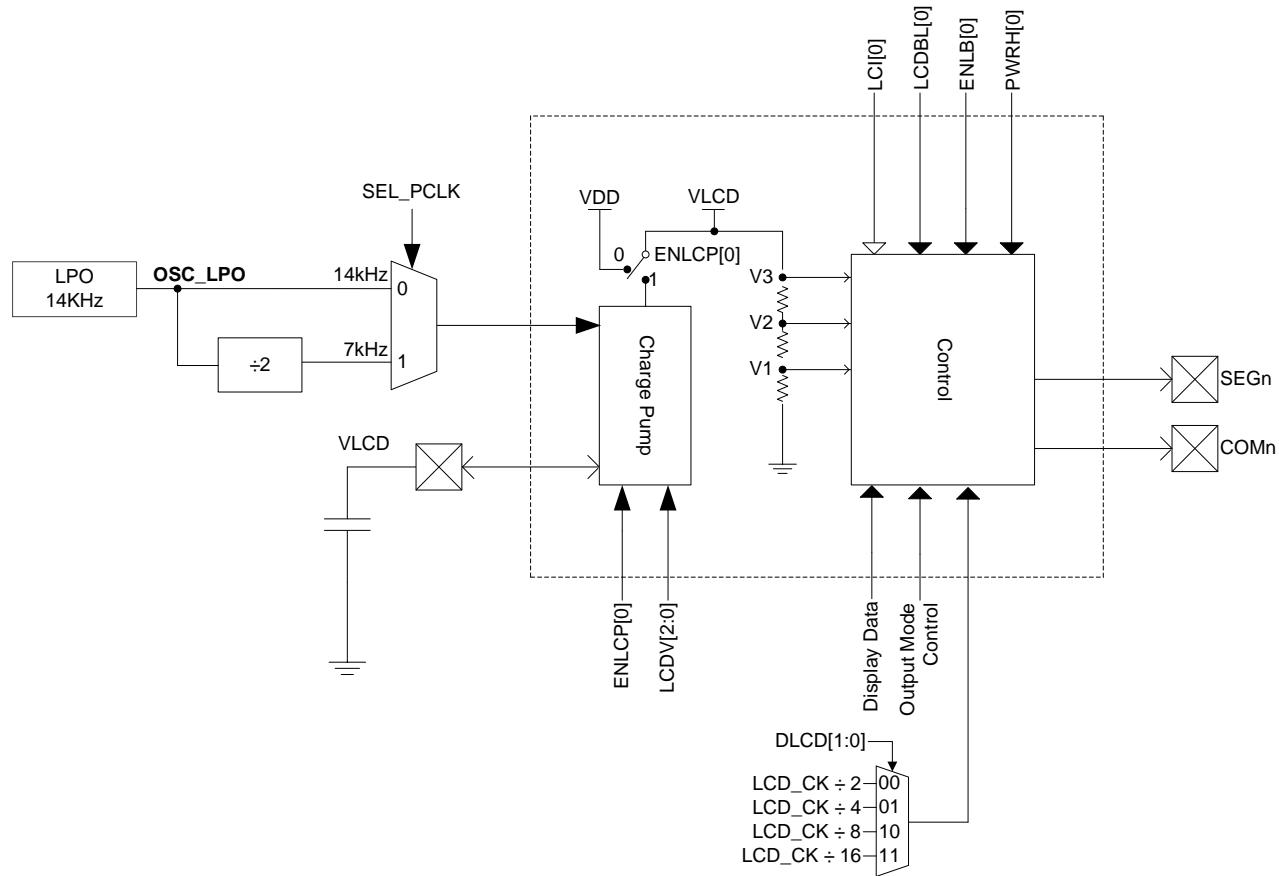


Figure 4-145 LCD block diagram

4.16. EUART

EUART TRANSMIT BLOCK DIAGRAM

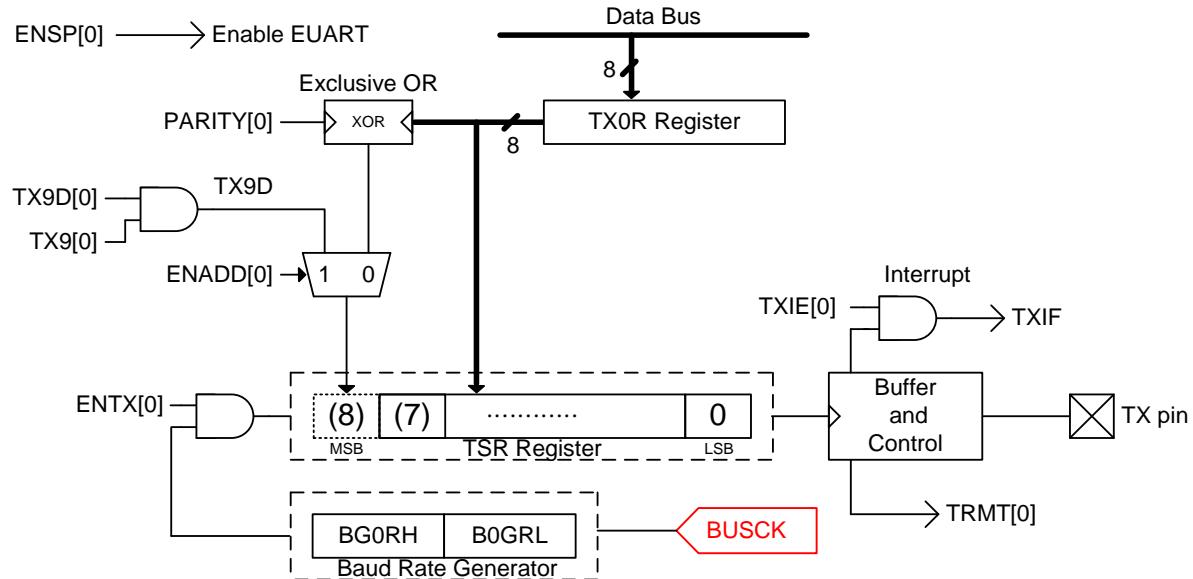


Figure 4-156 EUART transmit block diagram

EUART 8-BITS RECEIVE BLOCK DIAGRAM

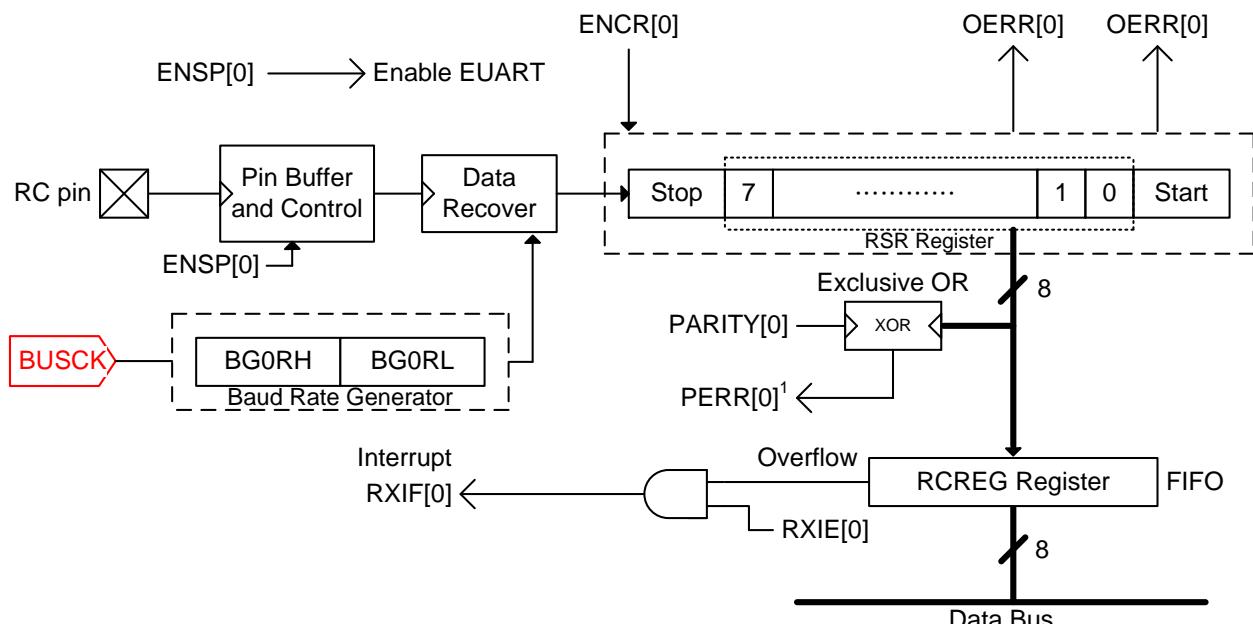


Figure 4-167 EUART 8-bits receive block diagram

4.17. I²C

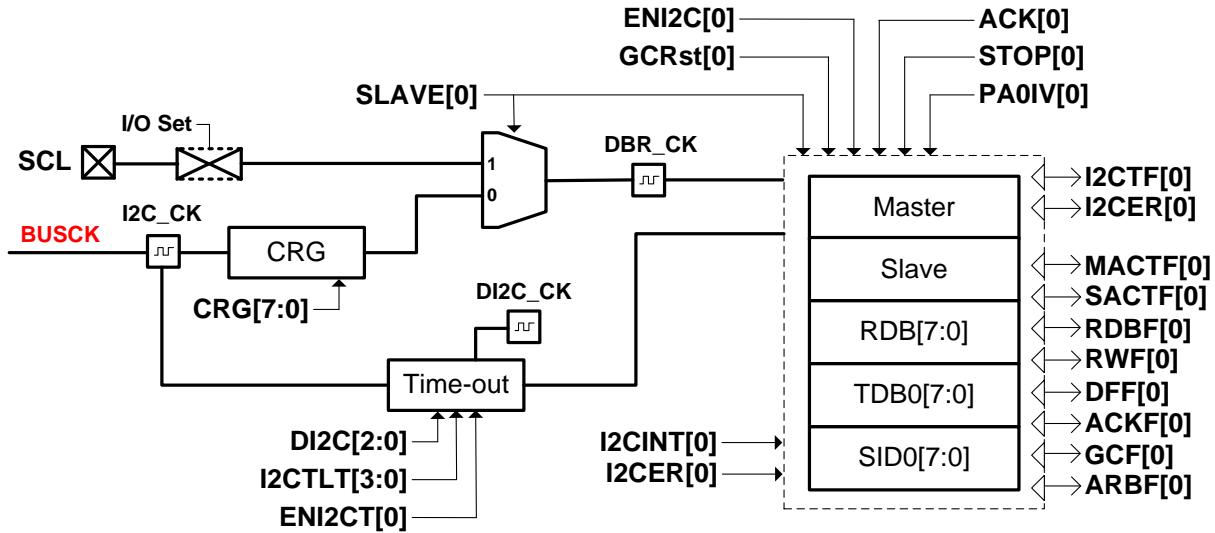


Figure 4-178 I²C block diagram

6. Electrical Characteristics

Absolute Maximum Ratings:

Absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Voltage applied at V _{DD} to V _{SS}	-0.2 V to 6.0 V
Voltage applied to any pin	-0.2 V to V _{DD} + 0.3 V
Voltage applied to RST/VPP pin	-0.2 V to 8.75 V
Diode current at any device terminal	±2 mA
Storage temperature, T _{stg} : (unprogrammed device)	-55°C to 125°C
(Programmed device)	-40°C to 85°C
Total power dissipation.....	0.5W
Maximum output current sink by any I/O pin	20mA

6.1. Recommended operating conditions

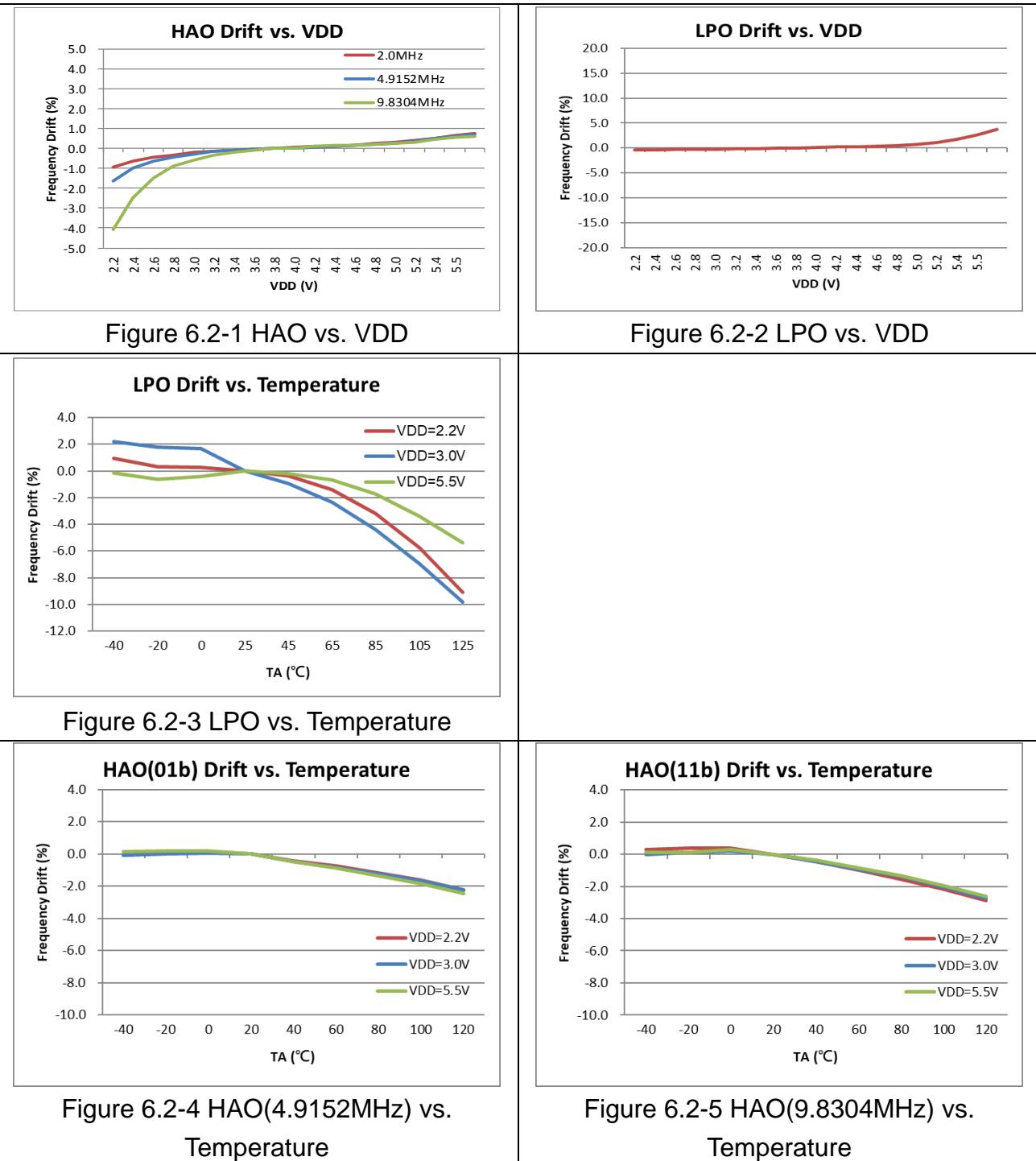
T_A = -40°C ~ 85°C, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
V _{DD}	Supply Voltage	All digital peripherals and CPU V _{DD} = 2.2V~5.5V, Frequency<=9.6MHz, V _{DD} = 3.6V~5.5V, Frequency<=16MHz,		2.2	5.5		V
V _{DDA}	Supply Voltage	Analog peripherals		2.4	4.5		
V _{SS}	Supply Voltage			0	0		
XT	External Oscillator Frequency	Watch crystal	V _{DD} = 2.5V~5.5V, ENXT[0]=1	XTS[1:0]=0x	32768		Hz
		Ceramic resonator, Crystal		XTS[1:0]=10	450K	4M	
				XTS[1:0]=11	1M	8M	
	Ceramic resonator, Crystal	V _{DD} = 3.6V~5.5V, ENXT[0]=1	XTS[1:0]=11	450K	16M		

6.2. Internal RC Oscillator

T_A = 25°C, VDD = 3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
HAO	High Speed Oscillator frequency	ENHAO[0]=1, HAOM[1:0]=01		-20%	4.9152	+20%	MHz
		ENHAO[0]=1, HAOM[1:0]=11		-20%	9.8304	+20%	
LPO	Low Power Oscillator frequency	VDD supply voltage be enable LPO		-20%	14.5	+20%	kHz



6.3. Supply current into VDD excluding peripherals current

$T_A = 25^\circ C, V_{DD} = 3.0V, OSC_LPO = 14.5KHz$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{AM1}	Active mode 1	$OSC_CY = off, OSC_HAO = 9.8304MHz, CPU_CK = 9.8304MHz$		600	1000	uA
I_{AM2}	Active mode 2	$OSC_CY = off, OSC_HAO = 4.9152MHz, CPU_CK = 4.9152MHz$		320	650	uA
I_{LP1}	Low Power 1	$OSC_CY = off, OSC_HAO = off, CPU_CK = LPO,$		2	5	uA
I_{LP2}	Low Power 2	$OSC_CY = off, OSC_HAO = off, CPU_CK = LPO, Idle state$		1.0	2.5	uA
I_{LP3}	Low Power 3	$OSC_CY = off, OSC_HAO = off, CPU_CK = off, Sleep state$		0.25	1.0	uA
I_{LP4}	Low Power 4	$OSC_CY = 32768Hz, OSC_HAO = off, CPU_CK = 32768Hz, Idle state$		1.8	3.6	uA

OSC_CY : External Oscillator frequency.
OSC_HAO : Internal High Accuracy Oscillator frequency.
CPU_CK : CPU core work frequency.

$T_A = 25^\circ C, V_{DD} = 5.5V, OSC_LPO = 14.5KHz$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{AM1}	Active mode 1	$OSC_CY = off, OSC_HAO = 9.8304MHz, CPU_CK = 9.8304MHz$		1200	1800	uA
I_{AM2}	Active mode 2	$OSC_CY = off, OSC_HAO = 4.9152MHz, CPU_CK = 4.9152MHz$		720	1200	uA
I_{LP1}	Low Power 1	$OSC_CY = off, OSC_HAO = off, CPU_CK = LPO,$		4	10	uA
I_{LP2}	Low Power 2	$OSC_CY = off, OSC_HAO = off, CPU_CK = LPO, Idle state$		2.5	5	uA
I_{LP3}	Low Power 3	$OSC_CY = off, OSC_HAO = off, CPU_CK = off, Sleep state$		0.4	2	uA

Figure 6.3-1 I_{AM1} vs. VDD

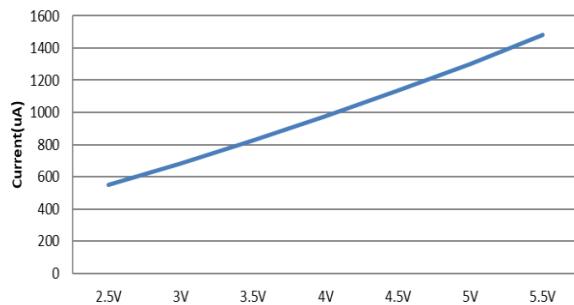


Figure 6.3-2 I_{AM2} vs. VDD

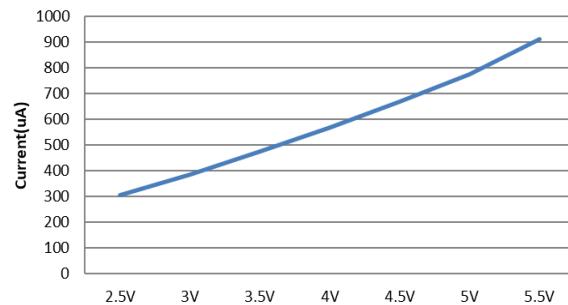


Figure 6.3-1 I_{AM1} vs. VDD

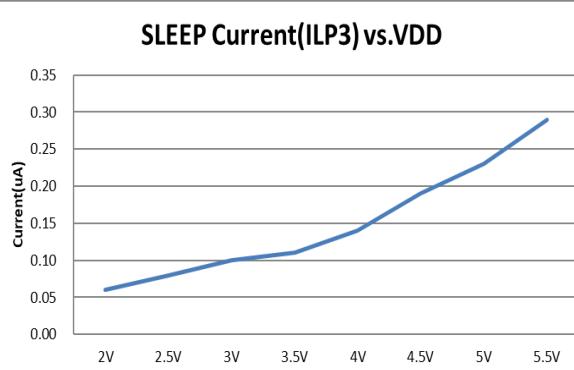


Figure 6.3-2 I_{AM4} vs. VDD

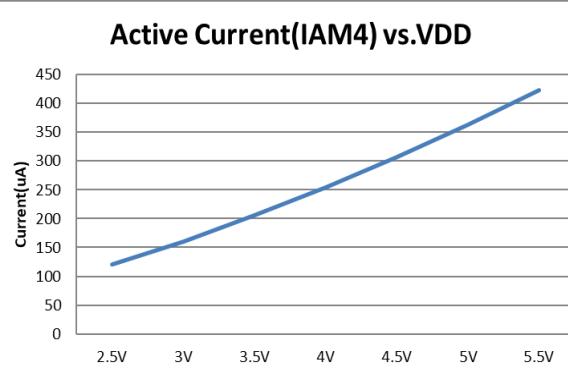


Figure 6.3-3 I_{AM3} vs. VDD

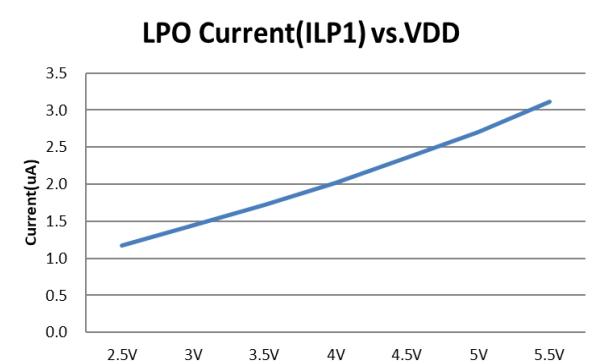


Figure 6.3-4 I_{AM4} vs. VDD

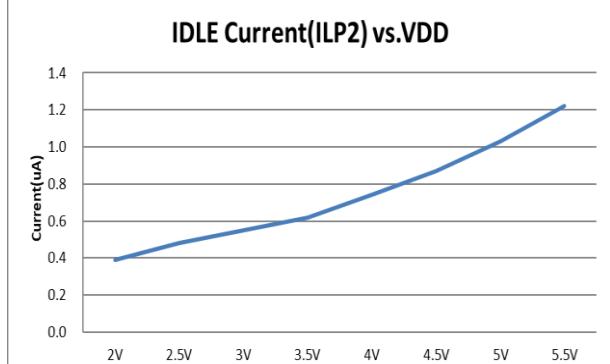


Figure 6.3-5 I_{LP1} vs. VDD

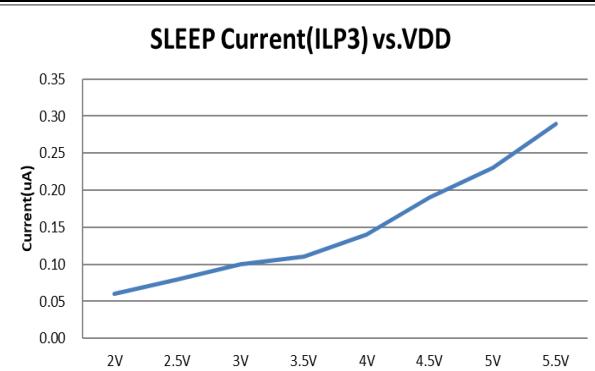


Figure 6.3-7 I_{LP3} vs. VDD

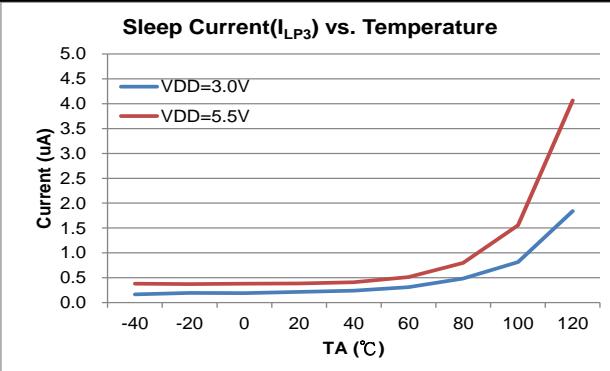


Figure 6.3-8 I_{LP3} vs. Temperature

6.4. Port 1,2,3,6,8

$T_A = 25^\circ C$, $VDD = 3.0V$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Input voltage and Schmitt trigger and leakage current and timing						
V_{IH}	High-Level input voltage			$0.7*V_{DD}$		V
V_{IL}	Low-Level input voltage		$0.3*V_{DD}$			
V_{hys}	Input Voltage hysteresis($V_{IH} - V_{IL}$)			$0.3*V_{DD}$		V
I_{LKG}	Leakage Current			0.1		uA
R_{PU}	Port pull high resistance		60			k Ω
Output voltage and current and frequency						
V_{OH}	High-level output voltage	$VDD=3V, I_{OH}=-10mA$	$V_{DD} -0.4$			V
		$VDD=5V, I_{OH}=-15mA$	$V_{DD} -0.4$			
V_{OL}	Low-level output voltage	$VDD=3V, I_{OL}=10mA$		$V_{SS} +0.4$		
		$VDD=5V, I_{OL}=15mA$		$V_{SS} +0.4$		

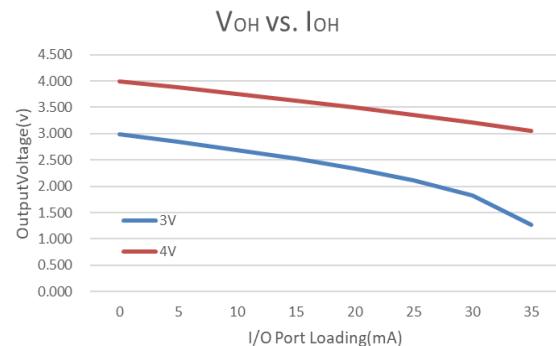


Figure 6.4-1 V_{OH} vs. I_{OH}

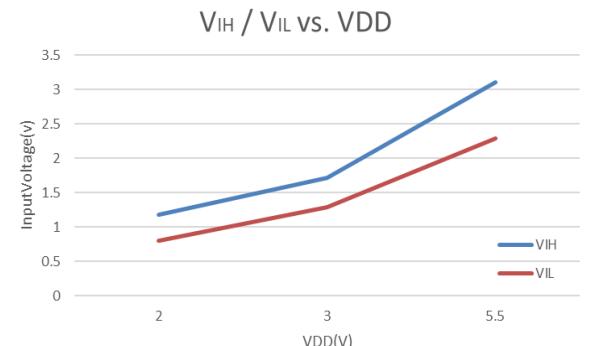


Figure 6.4-2 V_{IH}/V_{IL} vs. VDD

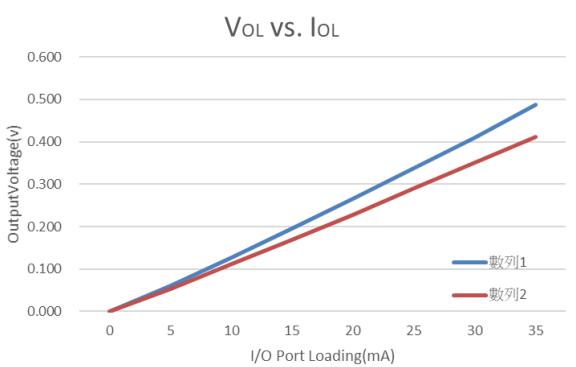


Figure 6.4-3 V_{OL} vs. I_{OL}

6.5. Reset(Brownout)

$T_A = 25^\circ C$, VDD = 3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions			Min.	Typ.	Max.	unit
BOR1	Pulse length needed to accepted reset internally, t_{d-LVR1}				2			uS
	V_{DD} Start Voltage to accepted reset internally ($L \rightarrow H$), V_{HYS1}				1.0	1.35	1.65	V
	BOR1 current, I_{BOR1}				0.2	0.5	0.5	uA
	Temperature Drift				5			%
BOR2	Pulse length needed to accepted reset internally, t_{d-LVR2}				2			uS
	V_{DD} Start Voltage to accepted reset internally ($L \rightarrow H$), V_{HYS2} , and BOR_TH[2:0]:	000b	-8%	1.73	+8%			V
		001b	-8%	2.0	+8%			
		010b	-8%	2.22	+8%			
		011b	-8%	2.5	+8%			
		100b	-8%	2.72	+8%			
		101b	-8%	3.0	+8%			
		110b	-10%	3.63	+10%			
		111b	-10%	4.0	+10%			
	V_{DD} Start Voltage to accepted reset internally ($H \rightarrow L$), V_{LVR2} , and BOR_TH[2:0]:	000b	-8%	1.67	+8%			V
		001b	-8%	1.96	+8%			
		010b	-8%	2.17	+8%			
		011b	-8%	2.44	+8%			
		100b	-8%	2.69	+8%			
		101b	-8%	2.96	+8%			
		110b	-10%	3.58	+10%			
		111b	-10%	3.94	+10%			
	Hysteresis, $V_{HYS2-LVR2}$	25	60	90				mV
	BOR2 current, I_{BOR2}	10	10	15				uA
	Temperature Drift	3	3	5				%
RST	Pulse length needed as RST/VPP pin to accepted reset internally, t_{d-RST}	2						uS
	Input Voltage to accepted reset voltage	1.1						V
	Reset release voltage	2						V
BOR1/BOR2 : Brownout Reset 1/2								
LVR : Low Voltage Reset of BOR								
RST : External Reset pin								

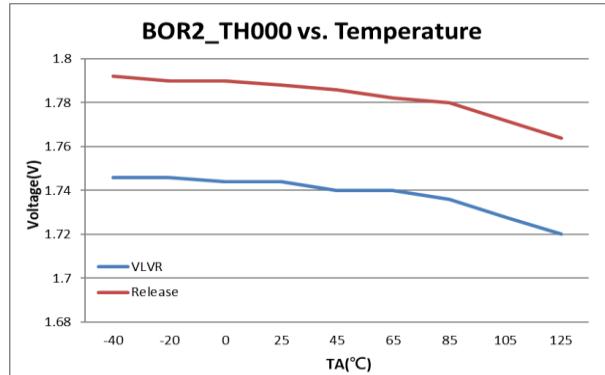
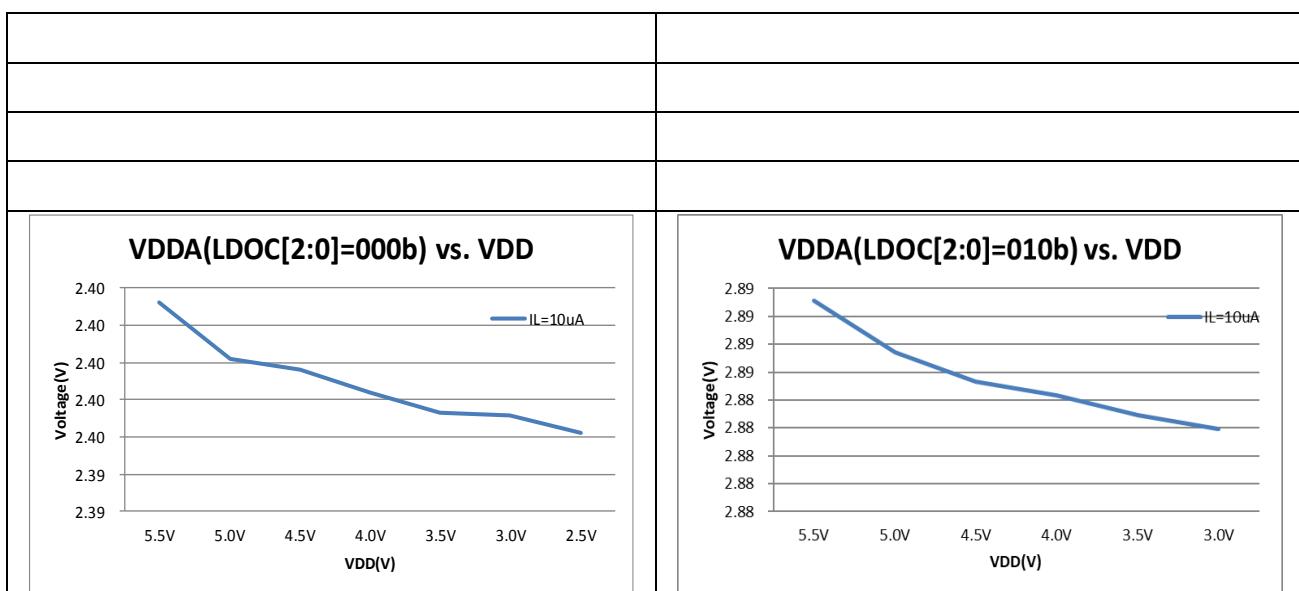


Figure 6.5-1 BOR vs. Temperature

6.6. Power System

$T_A = 25^\circ C$, VDD = 3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
VDDA	VDDA operation current, I_{VDDA}	$I_L = 0mA$	LDOC[2:0]=000b		20		uA
	Select VDDA output voltage	$I_L = 0.1mA$, $VDD \geq VDDA + 0.25V$	LDOC [2:0]=000b	-5%	2.4	+5%	V
			LDOC [2:0]=001b		2.6		V
			LDOC [2:0]=010b		2.9		V
			LDOC [2:0]=011b		3.3		V
			LDOC [2:0]=100b		3.6		V
			LDOC [2:0]=101b		4.0		V
			LDOC [2:0]=110b		4.5		V
	Dropout voltage	$I_L = 10mA$	LDOC [2:0]=000b		250		mV
	Temperature drift	$I_L = 0.1mA$	LDOC [2:0]=000b	$T_A = -40^\circ C \sim 85^\circ C$			PPM/ $^\circ C$
	V_{DD} Voltage drift		LDOC [2:0]=000b	$V_{DD} = 2.2V \sim 5.5V$			%/V
AGND	AGND operation current, I_{AGND}	SAGND≠000b	$I_L = 0mA$		400		uA
	Output voltage, V_{AGND}	SAGND=001b	$I_L = 0uA$	-5%	$VDDA * 0.3$	-5%	V
		SAGND=010b	$I_L = 0uA$	-5%	$VDDA * 0.1$	-5%	V
		SAGND=011b	$I_L = 0uA$	-5%	$VDDA * 0.5$	-5%	V
		SAGND=100b	$I_L = 0uA$	-5%	$VDDA * 0.4$	-5%	V
REFO	REFO operation current, I_{AREFO}		$I_L = 0uA$		260		uA
	V(REFO,VSS)		$I_L = 0uA$	-3%	1,2	-3%	V
	Temperature drift			$T_A = -40^\circ C \sim 85^\circ C$		100	ppm/ $^\circ C$
	RMS Noise					60	uVrms
VDDA : Adjust Voltage Regulator,							



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Figure 6.6-1 VDDA(000b) vs. VDD

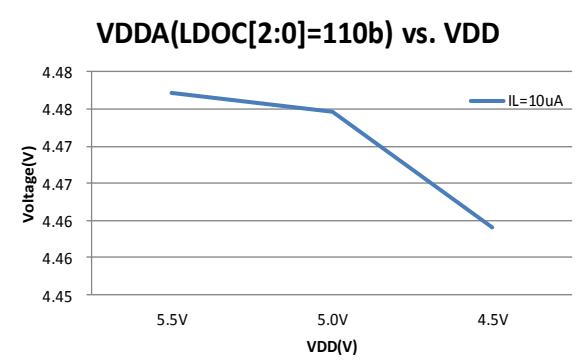


Figure 6.6-2 VDDA(010b) vs. VDD

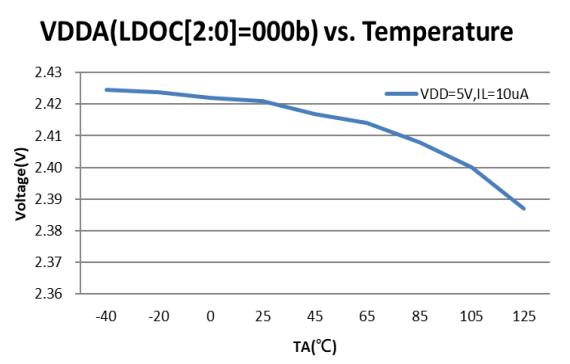


Figure 6.6-3 VDDA(110b) vs. VDD

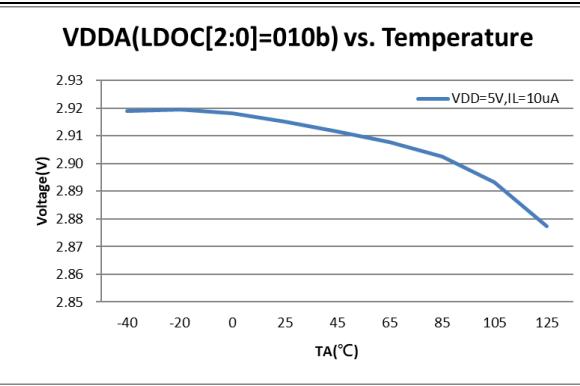


Figure 6.6-4 VDDA(000b) vs. Temperature

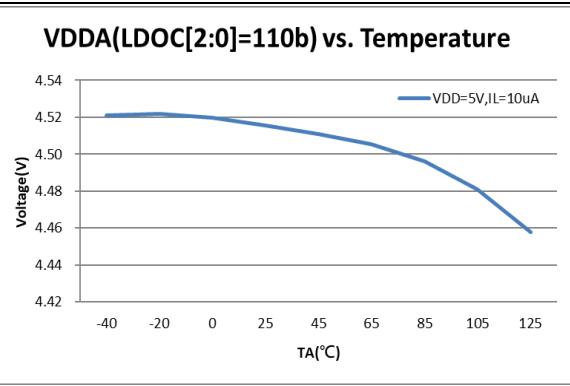


Figure 6.6-5 VDDA(010b) vs. Temperature

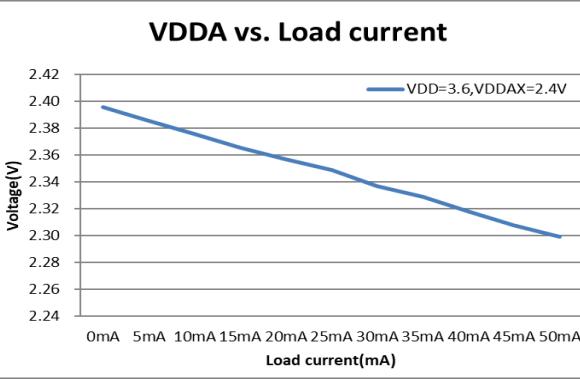


Figure 6.6-6 VDDA(110b) vs. Temperature

Figure 6.6-7 VDDA vs. Load current

6.7. Multi-Function Comparator

TA = 25°C, VDD = 3.0V, unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
IMC	Operation supply current	ENCMP[0]=1, CMPHS[0]=1b		5		uA
	Low Power Mode	ENCMP[0]=1, CMPHS [0]=0b		1		
VIC	Common-mode input voltage		0		VDD-1	V
VOS	Offset voltage		-5		5	mV
Vhys	Input hysteresis		0	0.7	1.5	mV
Vaccy	Reference Voltage	ENLDO[0]=1b, CPPS[1:0]=11b, VRSEL[0]=1b	1.15	1.2	1.25	V
	Temperature Drift			50		ppm/°C
	VDD Voltage drift			±0.2		%/V
IR	Multi-node resistor current	CPRL[0]=0b		10		uA
		CPRL[0]=1b		30		
	ENLDO[0]=1b, CPPS[1:0]=11b, CPRH [1:0]=01b, CPRL[0]=0b.	CPDA[4:0]=00011b	-5% 5%	3.89		V
		CPDA[4:0]=00100b		3.73		
		CPDA[4:0]=00101b		3.58		
		CPDA[4:0]=00110b		3.44		
		CPDA[4:0]=00111b		3.31		
		CPDA[4:0]=01000b		3.19		
		CPDA[4:0]=01001b		3.08		
		CPDA[4:0]=01010b		2.98		
		CPDA[4:0]=01011b		2.88		
		CPDA[4:0]=01100b		2.79		
		CPDA[4:0]=01101b		2.71		
		CPDA[4:0]=01110b		2.63		
		CPDA[4:0]=01111b		2.55		
		CPDA[4:0]=10000b		2.48		
		CPDA[4:0]=10001b		2.42		
		CPDA[4:0]=10010b		2.35		
		CPDA[4:0]=10011b		2.29		
		CPDA[4:0]=10100b		2.24		
		CPDA[4:0]=10101b		2.18		
		CPDA[4:0]=10110b		2.13		
		CPDA[4:0]=10111b		2.08		
		CPDA[4:0]=11000b		2.03		
		CPDA[4:0]=11001b		1.99		
		CPDA[4:0]=11010b		1.94		

	CPDA[4:0]=11011b	1.90	
	CPDA[4:0]=11100b		
	CPDA[4:0]=11101b		
	CPDA[4:0]=00000b~00010b, and 11110b~11111b (reserved)		

LVD : Low Voltage Detect.

6.8. LCD

 $T_A = 25^\circ C, V_{DD} = 3.3V, C_{VLCD} = 4.7\mu F$, unless otherwise noted.

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
I_{LCD}	Operation supply current with output buffer.(all segment turn on, No load)	ENLCP[0]=1	$V_{DD} = 3.0V$	8			uA
VLCD	Supply Voltage at VLCD pin	ENLCP [0]=0		2.4	5		V
	Embedded Charge Pump output voltage at VLCD pin	V _{DD} = 3.3V, ENLCP [0]=1, $C_{VLCD} = 4.7\mu F$	LCDV[2:0]=111b	-10%	2.45	+10%	V
			LCDV[2:0]=110b	-10%	2.70	+10%	
			LCDV[2:0]=101b	-10%	2.85	+10%	
			LCDV[2:0]=100b	-10%	3.10	+10%	
			LCDV[2:0]=011b	-10%	3.30	+10%	
			LCDV[2:0]=010b	-10%	4.10	+10%	
			LCDV[2:0]=001b ($V_{DD} > 2.4V$ mode)	-10%	4.55	+10%	
			LCDV[2:0]=000b ($V_{DD} > 2.75V$)	-10%	5.1	+10%	
Z_{LCD}	VDD Voltage drift	ENLCP [0]=1, $C_{VLCD} = 4.7\mu F$, LCDV[2:0]>010b, $V_{DD} = 2.2V \sim 5.5V$; LCDV[2:0]=001b, $V_{DD} > 2.4V$; LCDV[2:0]=000b, $V_{DD} > 2.75V$;		4			%/V
				10			k Ω

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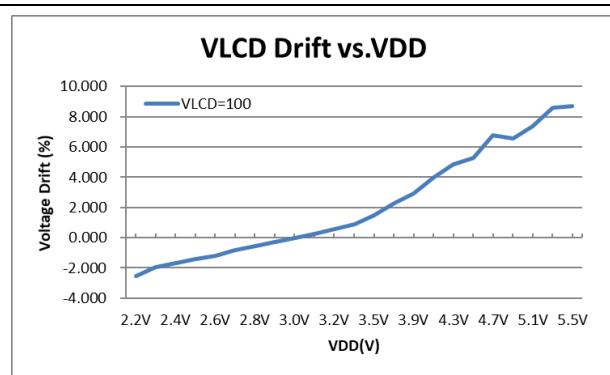


Figure 6.8-1 VLCD(LCDV=100b) vs. VDD

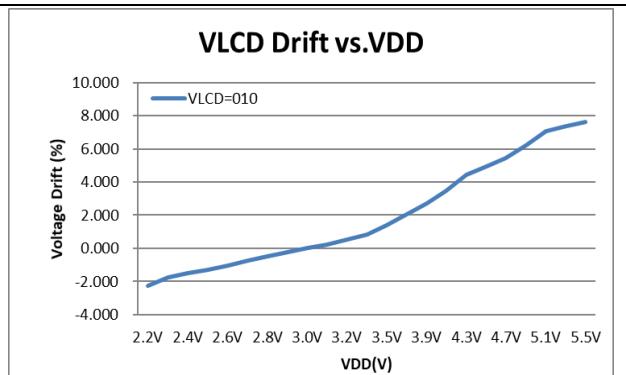


Figure 6.8-2 VLCD(LCDV=010b) vs. VDD

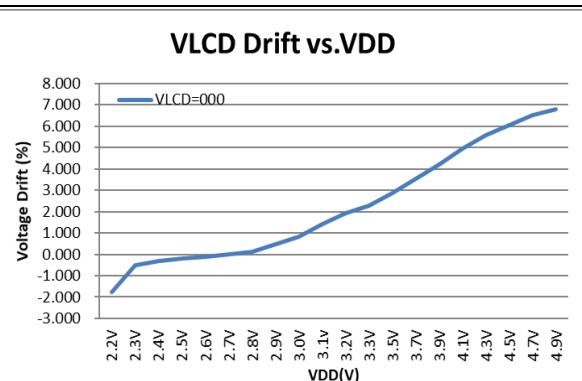


Figure 6.8-3 VLCD(LCDV=000b) vs. VDD

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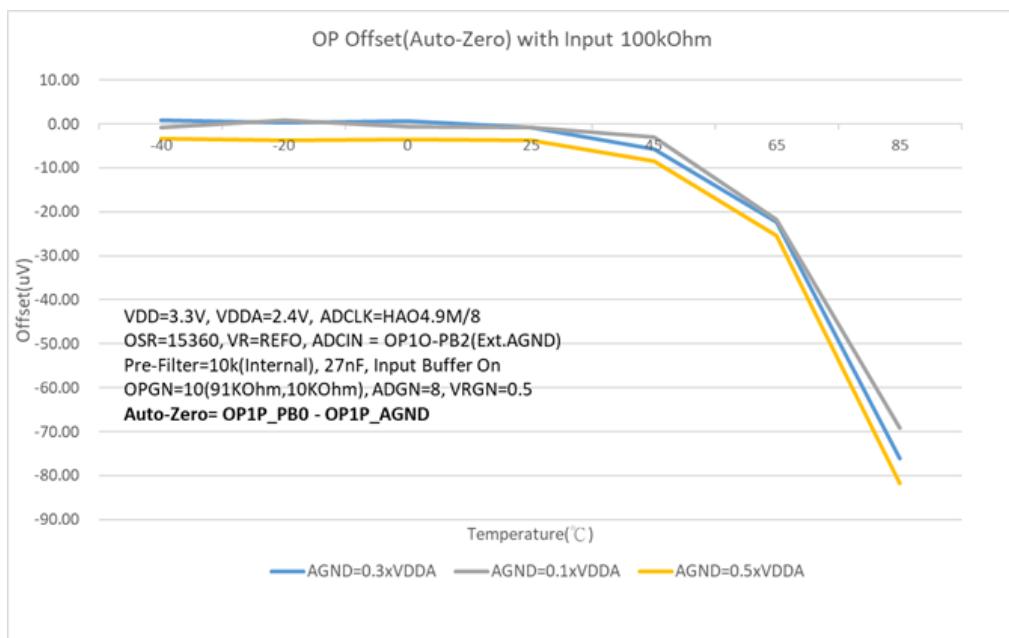
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6.9. OPAMP

TA = 25°C, VDD = 3.3V, VDDA=2.4V, AGND=0.3VDDA, Input buffer on unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{os-op}	Input offset voltage	OP Gain=10, ADGN=8, VRGN=0.5 Pre-Filter=10K(Inside) / 27nF(Outside)			800	uV
	Input offset voltage with Auto-Zero	Auto-Zero(OP1P_PB0-OP1P_AGND) OP Gain=10, ADGN=8, VRGN=0.5 Pre-Filter=10K(Inside) / 27nF(Outside)		-2		uV
V_{os-td}	OP Input offset temperature drift	with chopper, TA=-40°C ~ 85°C		0.64		uV/°C
CMVR	Common-mode voltage input range		VSS+0.1		VDDA - 1.1	V



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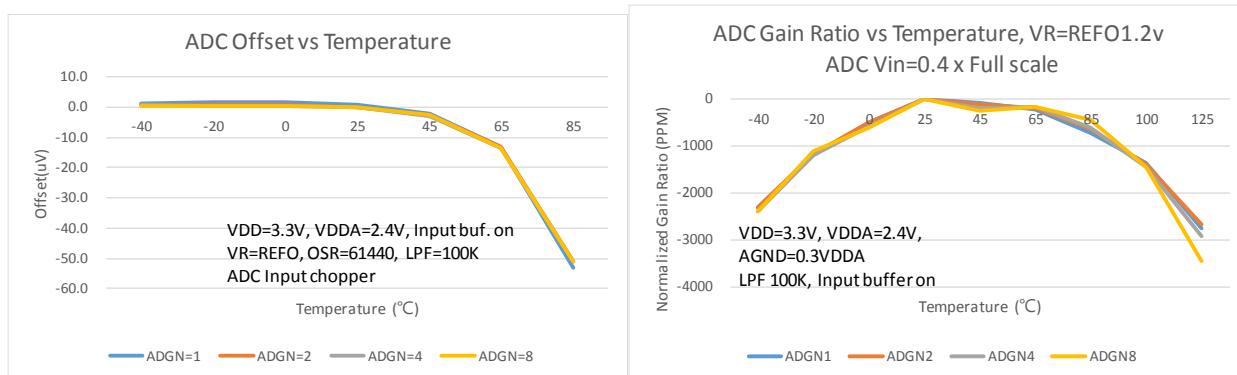
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6.10. Σ ADC, Power Supply and recommended operating conditions

TA = 25°C, VDD = 3.0V, VDDA=2.4V,unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit		
V _{SD18}	Supply Voltage at VDDA	ENLDO[0]=0			2.4	5.5	V		
I _{ΣADC}	Operation supply current	Input gain =1, input buffer on		254		uA			
f _{ΣADC}	Modulator sample frequency, ADC_CK			1		MHz			
	Over Sample Ratio, OSR			32	61440				
Eos	Input offset voltage	Chopper on OSR=61440	Input gain=1, reference gain=1	1		uV			
Vrms	Input RMS Noise	Chopper on, OSR=61440, input gain=1 reference gain=1			3.5		uV		
		Chopper off, OSR=32, input gain=1 reference gain=1			350		uV		
NM	Normal Rejection ratio	Chopper On OSR=61440	Input gain=1, reference gain=1. Vin=200mVrms 50/60Hz	60		dB			
AC _{bw}	AC Measurement Bandwidth	OSR=32, LPFBW=1024 Without Voltage Divider	0.5% error	20	4k	Hz			
			3dB						
			Square wave, 0.5% error	0.3k					
			Triangle wave, 0.5% error						



6.10.1. Σ ADC, Temperature Sensor

$T_A = 25^{\circ}\text{C}$, $V_{DD} = 3.0\text{V}$, $VDDA=2.4\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
TC_s	Sensor temperature drift			173		$\mu\text{V}/^{\circ}\text{C}$
KT	Absolute Temperature Scale 0°K			284		$^{\circ}\text{C}$
TC_{ERR}	One point calibrate error temperature	Calibration at 25°C of $-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$		± 2		$^{\circ}\text{C}$

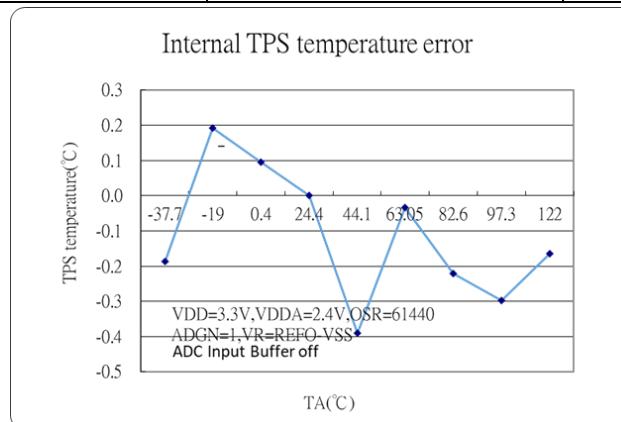


Figure 6.10-2 ADC Temperature Error

6.11. Analog input and switch performance

$T_A = 25^{\circ}\text{C}$, $V_{DD} = 3.0\text{V}$, $VDDA=2.4\text{V}$ AGND=0.5VDDA unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{AL}	Analog Input Leakage Current	AGND=0.5 VDDA		10	100	pA
		AGND=0.3VDDA		10	100	
		AGND=0.1VDDA		100	500	

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6.12. Build-In EPROM(BIE)

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{BIE}	Supply Voltage at VPP PIN		8.5	8.75		V
I_{BIE}	Operation supply current		3			mA
V_{SS}	Supply Voltage		0			V

When connecting to the external V_{BIE} power source to program the BIE block, users can use the instruction to program the words one by one into the BIE block.

6.13. Build-In EPROM(BIE) Low voltage control circuit

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.05\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
T_O	Operation temperature range		0	25	40	°C
V_{DD}	Operation supply Voltage		2.75		5.5	V
V_{SS}	Supply Voltage		0			V

When the 2.75V low voltage programming control circuit is activated, users can program the BIE block without connecting to the external V_{BIE} power source.

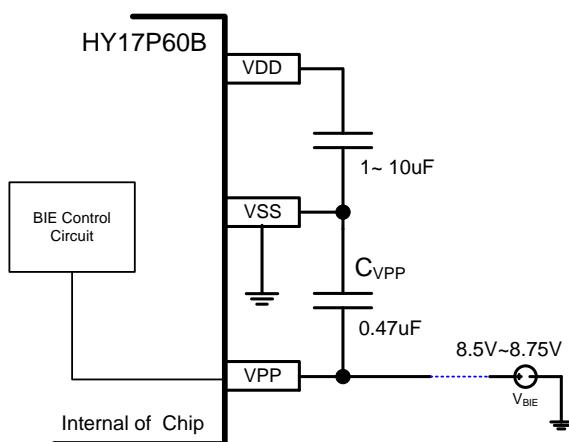


Figure 6.13-1 BIE typical application block diagram

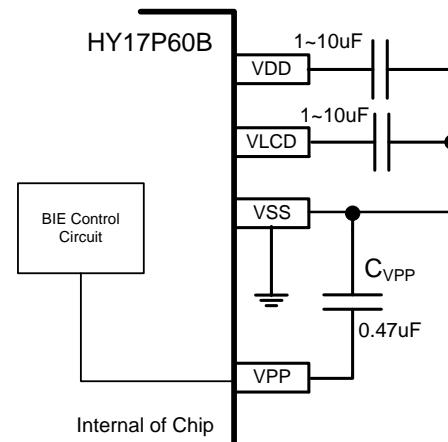


Figure 6.13-2 BIE typical application use low voltage control circuit block diagram

HY17P60B

8-Bit RISC-like Mixed Signal Microcontroller

Embedded 19-Bit $\Sigma\Delta$ ADC with LNA OPAMP & 4x20 LCD



7. Ordering Information

Device ¹	Package Type	Pins	Package Drawing		Code ²	Shipment Packing Type	Unit Q'ty	Material Composition	MSL3
HY17P60B-D000	Die	-	D	000	000	Tray	250	Green ⁴	-
HY17P60B-L064	LQFP	64	L	064	000	Tray	250	Green ⁴	MSL-3
HY17P60B-NS32	QFN	32	N	S32	000	Tape & Reel	5000	Green ⁴	MSL-3

¹ Device No.: Model No. – Package Type Description – Code (Blank Code/ Standard/ Customized Programming Code)

Ex: Your customized programming code is 001 and you require die shipment.

The device No. will be HY17P60B-D000-001.

Ex: You request blank code in die package.

The device No. will be HY17P60B-D000.

Ex: You request blank code in LQFP 64 package.

The device No. will be HY17P60B-L064.

And please clearly indicate the shipment packing type when placing orders.

Ex: Your customized programming code is 008 and you require products in LQFP 64 package.

The device No. will be HY17P60B-L064-008.

And please clearly indicate the shipment packing type when placing orders.

² Code :

“001”~“999” is standard or customized programming code. Blank code does not have these numbers.

³ MSL:

The Moisture Sensitivity Level ranking conforms to IPC/JEDEC J-STD-020 industry standard categorization.

The products are processed, packed, transported and used with reference to IPC/JEDEC J-STD-033.

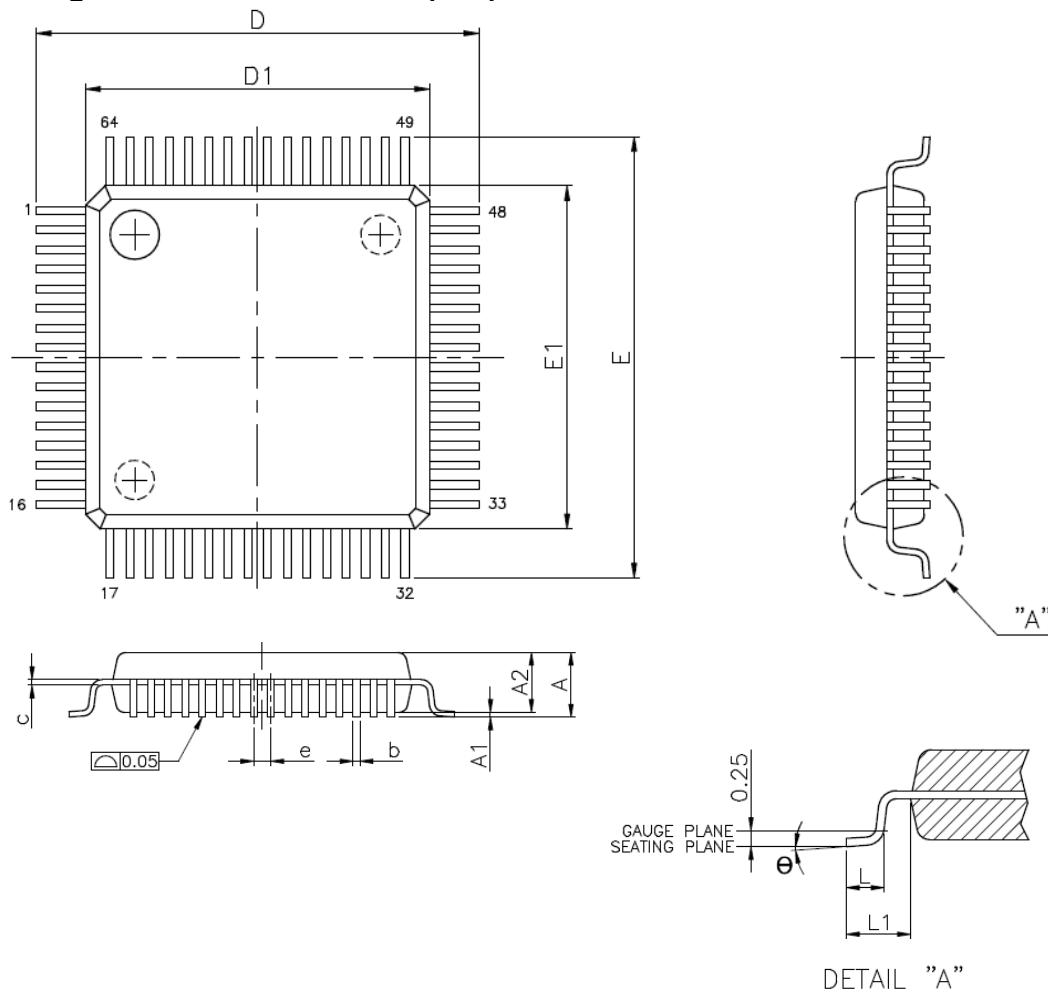
⁴ Green (RoHS & no Cl/Br):

HYCON products are Green products that compliant with RoHS directive and are Halogen free (Br<900ppm or Cl<900ppm or (Br+Cl)<1500ppm).

8. Package Information

8.1. LQFP64(L064)

8.1.1. Package Dimensions LQFP64(7x7)



SYMBOLS	MIN.	NOM.	MAX.
A	—	—	1.60
A1	0.05	—	0.15
A2	1.35	1.40	1.45
b	0.13	0.18	0.23
c	0.09	—	0.20
D	9.00 BSC		
D1	7.00 BSC		
e	0.40 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		
Θ	0°	3.5°	7°

Note:

1. All dimensions refer to JEDEC OUTLINE MS-026.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.

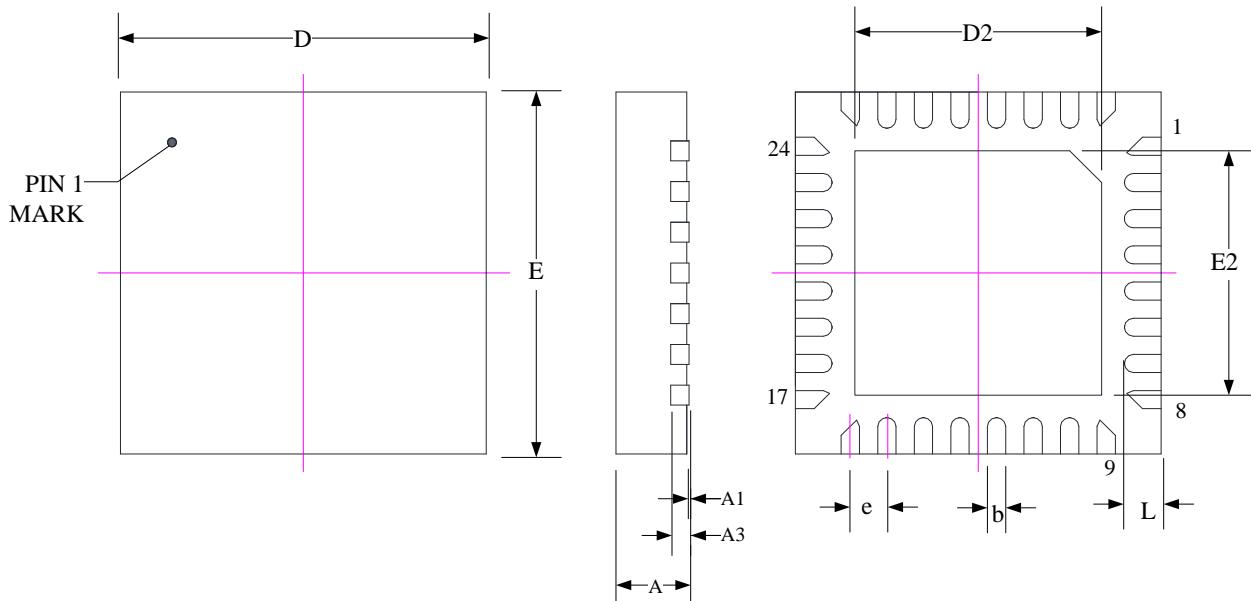
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8.2. QFN32(NS32)

8.2.1. Package Dimensions QFN32(4x4x0.55)

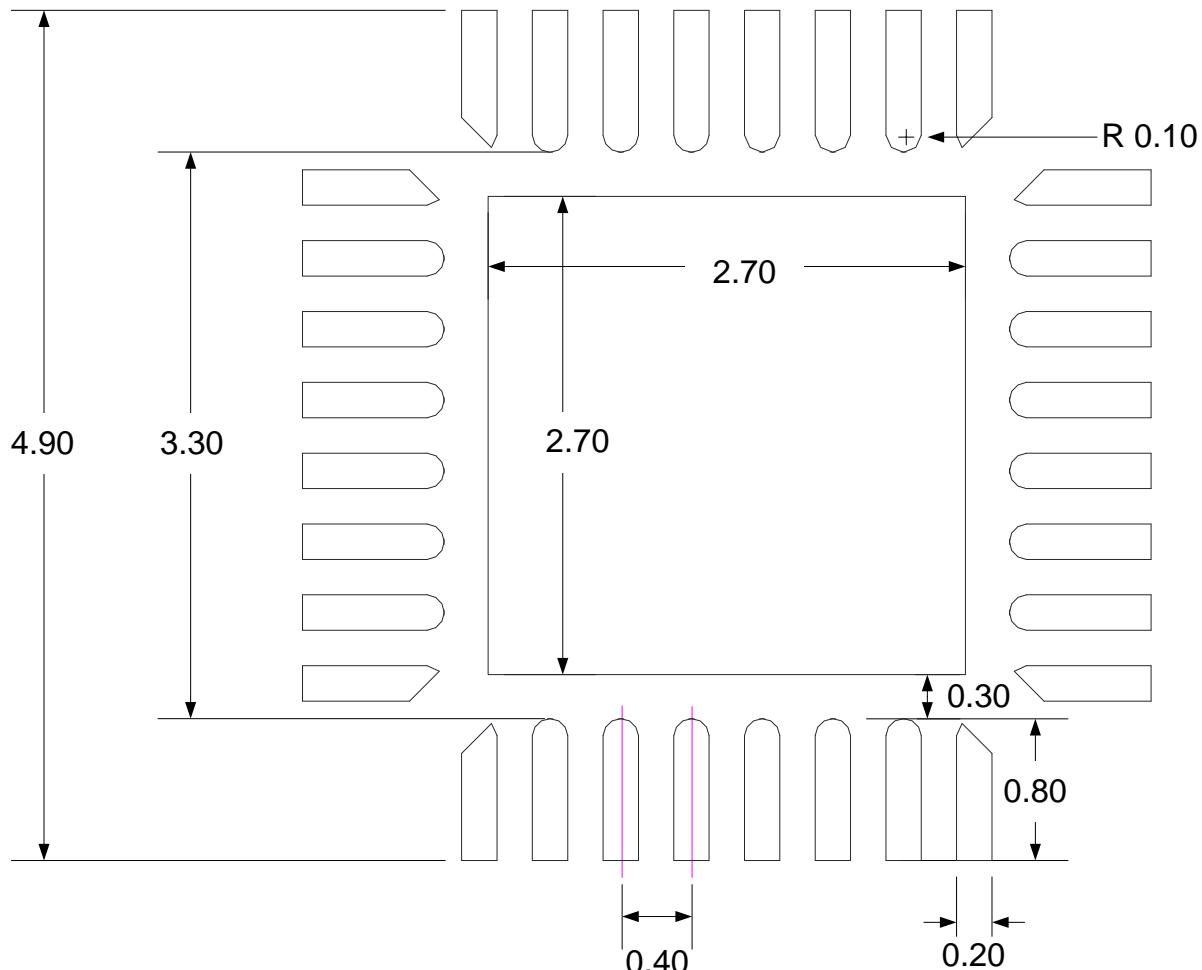


SYMBOLS	MIN	NOM	MAX
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A3	0.15 REF.		
b	0.15	0.20	0.25
D	3.90	4.00	4.10
E	3.90	4.00	4.10
D2	2.65	2.70	2.75
E2	2.65	2.70	2.75
L	0.25	0.30	0.35
e	0.40 BASIC		

Note:

1. All dimensions refer to JEDEC OUTLINE MO-220.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.
4. https://www.hycontek.com/hy_mcu/QFN_DFN_PCB_EN.pdf

8.2.2. Land Pattern Design Recommendations



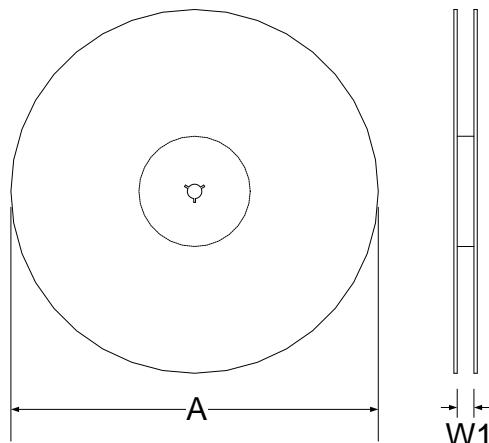
Note:

1. Publication IPC-7351 is recommended for alternate designs.
2. https://www.hycontek.com/wp-content/uploads/QFN_DFN_PCB_EN.pdf
3. Unit: mm.

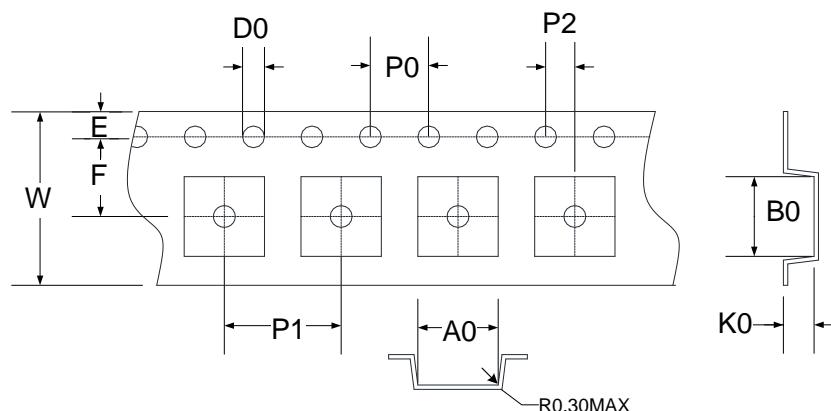
8.2.3. Tape & Reel Information

8.2.3.1. Reel Dimensions

Unit: mm



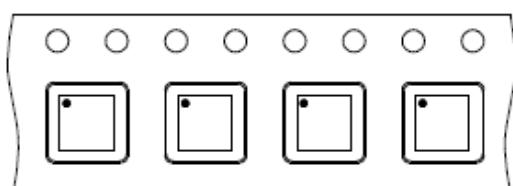
8.2.3.2. Carrier Tape Dimensions



SYMBOLS	Reel Dimensions		Carrier Tape Dimensions										
	A	W1	A0	B0	K0	P0	P1	P2	E	F	D0	W	
Spec.	330	12.5	4.35	4.35	1.10	4.00	8.00	2.00	1.75	5.50	1.50	12.00	
Tolerance	+6/-3	+1.5/-0	± 0.10	± 0.10	± 0.10	± 0.10	± 0.10	± 0.10	± 0.05	± 0.10	± 0.05	$+0.1/-0$	± 0.30

Note: 10 Sprocket hole pitch cumulative tolerance is ± 0.20 mm.

8.2.3.3. Pin1 direction



9. Revision Record

Major differences are stated thereinafter:

Version	Page	Date	Revision Summary
V01	All	2021/09/22	First edition
V02	46	2022/03/21	Update the unit quantity of Die & QFN32 package type
	48	2022/03/21	Update the package dimensions of QFN32 package type to 4x4x0.55